

General Description

DA9223-A and DA9224-A are PMICs optimized for the supply of CPUs, GPUs, and DDR memory rails in automotive in-vehicle infotainment systems, Advanced Driver Assistance Systems (ADAS), navigation and telematics applications. The fast transient response (10 A/µs) and load regulation are optimized for the latest generation of multi core application processors.

DA9223-A operates as a single four-phase buck converter delivering up to 16 A output current.

DA9224-A integrates two dual-phase buck converters, capable of delivering 2 x 8 A output current.

Each buck regulates a programmable output voltage in the range of 0.3 V to 1.57 V. With an external resistor divider the output voltage can be set to any voltage between 1.57 V and 4.3 V. The input voltage range of 2.8 V to 5.5 V makes it suited for a wide variety of low voltage systems, including all Li-lon battery powered applications.

To guarantee the highest accuracy and to support multiple PCB routing scenarios without loss of performance, a remote sensing capability is implemented in both the DA9223-A and DA9224-A.

The power devices are fully integrated, so no external FETs or Schottky diodes are needed.

A programmable soft start-up can be enabled, which limits the inrush current from the input node and secures a slope controlled activation of the rail.

The Dynamic Voltage Control (DVC) supports adaptive adjustment of the supply voltage depending on the processor load, either via direct register writes through the communication interface (I²C or SPI compatible) or via an input pin.

DA9223-A and DA9224-A feature integrated over-temperature and over-current protection for increased system reliability without the need for external sensing components. The safety feature set is completed by a VDDIO under voltage lockout.

The configurable I²C address selection via GPI allows multiple instances of DA9223-A and DA9224-A to be placed in an application sharing the same communication interface with different addresses.

Key Features

- 2.8 V to 5.5 V input voltage
- 1 x 16 A DA9223-A
- 2 x 8 A DA9224-A
- 3 MHz nominal switching frequency (allows use of low profile [1 mm] inductors)
- ±1 % accuracy (static)
- ±3 % accuracy (dynamic)
- 0.3 V to 1.57 V output voltage
 1.57 V to 4.3 V with resistor divider

- Dynamic Voltage Control (DVC)
- Automatic phase shedding
- Integrated power switches
- Remote sensing at point of load
- I²C/SPI compatible interface
- Adjustable soft start
- -40 °C to +105 °C temperature range
- AEC-Q100 grade 2 qualified
- 66 TFBGA 0.8 mm pitch

Applications

- In-car infotainment
- Automotive display clusters
- Advanced Driver Assistance Systems (ADAS)
- Navigation and telematics
- Mobile computing
- Industrial embedded systems



System Diagrams

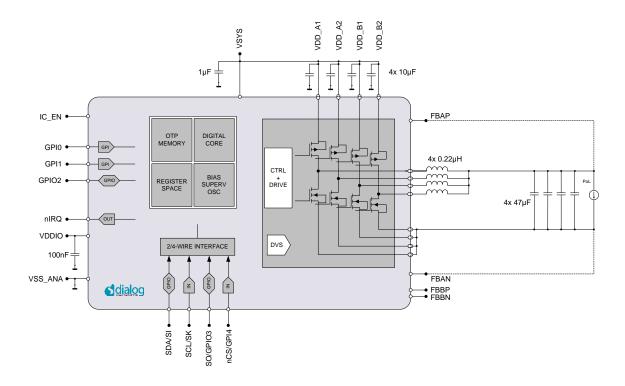


Figure 1: DA9223-A System Diagram

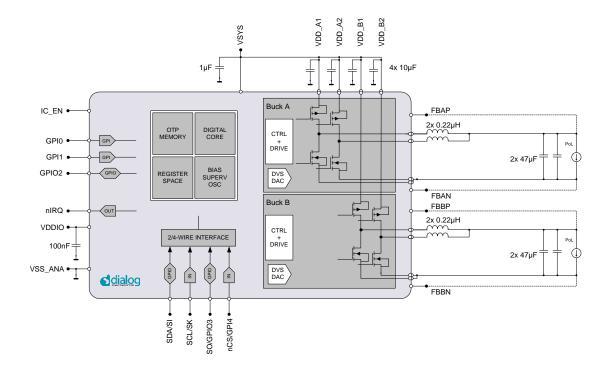


Figure 2: DA9224-A System Diagram



Contents

Ge	neral	Descrip	tion	
Ke	y Feat	tures		1
Аp	plicat	ions		1
Sy	stem	Diagram	ns	2
1	Term	ns and D	Definitions	6
2				
3			ximum Ratings	
			_	
4			led Operating Conditions	
5			naracteristics	
6		•	easurements	
7			Description	
	7.1	DC-DC	Buck Converter	
		7.1.1	Switching Frequency	
		7.1.2	Operation Modes and Phase Selection	
		7.1.3	Output Voltage Selection	25
		7.1.4	Soft Start Up	26
		7.1.5	Current Limit	26
		7.1.6	Variable VOUT above 1.57 V	26
	7.2	Ports D	Description	28
		7.2.1	VDDIO	28
		7.2.2	IC_EN	28
		7.2.3	nIRQ	28
		7.2.4	GPIO Extender	29
	7.3	Operati	ing Modes	31
		7.3.1	ON Mode	31
		7.3.2	OFF Mode	31
	7.4	Control	I Interfaces	32
		7.4.1	4-WIRE Communication	32
		7.4.2	2-WIRE Communication	36
		7.4.3	Details of the 2-WIRE Control Bus Protocol	37
	7.5	Interna	ll Temperature Supervision	39
8	Regi	ster Defi	initions	40
	8.1	Registe	er Map	40
	8.2	Registe	er Definitions	42
		8.2.1	Register Page Control	42
		8.2.2	Register Page 0	42
		8.2.3	Register Page 1	47
		8.2.4	Register Page 2	52
		8.2.5	Register Page 4	58
9	Appl	ication I	Information	59
	9.1	Capaci	itor Selection	59
	9.2	Inducto	or Selection	60



10	Pack	age Information6	31
	10.1	Package Outlines	31
	10.2	Package Marking6	32
11	Orde	ring Information6	32
Fig	gure	es e	
Fia	ure 1:	DA9223-A System Diagram	2
		DA9224-A System Diagram	
		66 TFBGA 0.8 mm Pitch Ball Map	
		66 TFBGA 0.8 mm Pitch Power Derating Curve	
		2-WIRE Bus Timing	
		DA9223-A Efficiency vs Load, Vout = 1.0 V, 0-16 A	
		DA9223-A Efficiency vs Load, V _{IN} = 3.6 V, 0-16 A	
		DA9224-A Efficiency vs Load, V _{OUT} = 1.0 V, 0-8 A	
		: DA9224-A Efficiency vs Load, V _{IN} = 3.6 V, 0-8 A	
		: Interface of DA9223-A/24-A with DA9063 and the Host Processor	
		2: Typical Application of DA9223-A	
Fig	ure וט ura 1/1	S: Typical Application of DA9224-A	25 25
Fia	ure 15	i: Resistive Divider from VOUT to FBAN	26
		Street Control of Operation (Example Paths)	
Fig	ure 17	: Schematic of 4-WIRE and 2-WIRE Power Manager Bus	32
Fig	ure 18	a: 4-WIRE Host Write and Read Timing (nCS_POL = '0', CPOL = '0', CPHA = '0')	34
Fig	ure 19	2: 4-WIRE Host Write and Read Timing (nCS_POL= '0', CPOL = '0', CPHA = '1')	34
Fig	ure 20	o: 4-WIRE Host Write and Read Timing (nCS_POL = '0', CPOL = '1', CPHA = '0') : 4-WIRE Host Write and Read Timing (nCS_POL = '0', CPOL = '1', CPHA = '1')	35
Fin	ure 21	: Timing of 2-WIRE START and STOP Condition	27 27
		S: 2-WIRE Byte Write (SDA Line)	
		Examples of 2-WIRE Byte Read (SDA Line)	
		Examples of 2-WIRE Page Read (SDA Line)	
		3: 2-WIRE Page Write (SDA Line)	
		2: 2-WIRE Repeated Write (SDA Line)	
Fig	ure 28	B: DA9223-A/24-A 66 TFBGA 0.8 mm Pitch Package Outline Drawing	וֹכ
Ta	bloc		
	bles		
		Pin Description	
		Pin Type Definition	
		Absolute Maximum Ratings	
		Recommended Operating Conditions	
		C Performance and Supervision	
		Digital I/O Characteristics1	
Tab	ole 8: 2	2-WIRE Control Bus Characteristics1	16
		4-WIRE Control Bus Characteristics	
		4-WIRE Clock Configurations	
		4-WIRE Interface Summary	
		Register Map	
		Recommended Capacitor Types	
Dat	ashe	Revision 2.7 09-Feb-202	22

DA9223-A and DA9224-A



Table 15: Recommended Inductor Types	60
Table 16: Package Marking	
Table 17: Ordering Information	62



1 Terms and Definitions

AP Application Processor
CPU Central Processing Unit

DDR Dual Data Rate

DVC Dynamic Voltage Control
FET Field Effect Transistor
GPI General Purpose Input
GPU Graphic Processing Unit

IC Integrated Circuit

OTP One Time Programmable memory

PCB Printed Circuit Board

PMIC Power Management Integrated Circuit

POL Point Of Load

PWM Pulse Width Modulation



2 Pinout

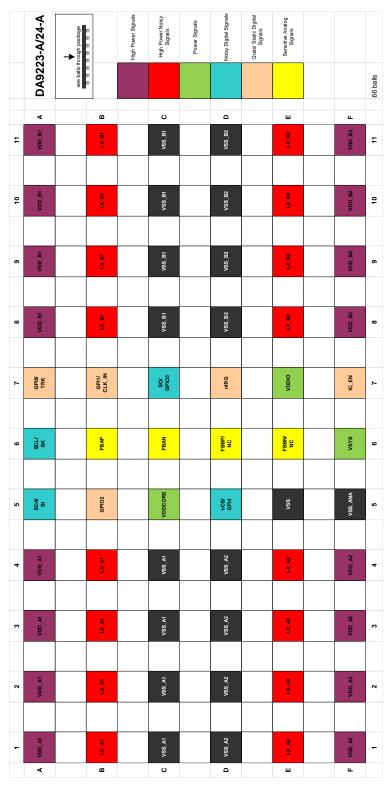


Figure 3: 66 TFBGA 0.8 mm Pitch Ball Map



Table 1: Pin Description

Pin Name	Signal Name	Second Function	Type (See Table 2)	Description
B1, B2, B3, B4	LX_A1		AO	Switching node for Buck A phase 1
E1, E2, E3, E4	LX_A2		AO	Switching node for Buck A phase 2
B8, B9, B10, B11	LX_B1		AO	Switching node for Buck B phase 1
E8, E9, E10, E11	LX_B2		AO	Switching node for Buck B phase 2
A1, A2, A3, A4	VDD_A1		PS	Supply voltage for Buck A phase 1 To be connected to VSYS
F1, F2, F3, F4	VDD_A2		PS	Supply voltage for Buck A phase 2 To be connected to VSYS
A8, A9, A10, A11	VDD_B1		PS	Supply voltage for Buck B phase 1 To be connected to VSYS
F8, F9, F10, F11	VDD_B2		PS	Supply voltage for Buck B phase 2 To be connected to VSYS
F7	IC_EN		DI	Integrated Circuit (IC) Enable Signal
D7	nIRQ		DO	Interrupt line towards the host
E7	VDDIO		PS	I/O Voltage Rail
B6	FBAP		Al	Positive sense node for Buck A
C6	FBAN		Al	Negative sense node for Buck A
D6	FBBP		Al	Positive sense node for Buck B of DA9224-A
	NC		AO	Do not connect for DA9223-A
E6	FBBN		AI	Negative sense node for Buck B of DA9224-A
	NC		AO	Do not connect for DA9223-A
A7	GPI0	TRK	DI/AI	General purpose input, input track
B7	GPI1		DI	General purpose input
B5	GPIO2		DIO	General purpose input/output
A5	SDA	SI	DIO	2-WIRE data, 4-WIRE data input/output
A6	SCL	SK	DI	2-WIRE clock, 4-WIRE clock
D5	nCS	GPI4	DI	4-WIRE chip select, general purpose input
C7	so	GPIO3	DIO	4-WIRE data output, general purpose input/output
C5	VDDCORE		AO	Regulated supply for internal circuitry. Decouple with 150 nF (or 220 nF)
F6	VSYS		PS	Supply for IC and input for voltage supervision
E5	VSS		VSS	
F5	VSS_ANA		VSS	



Pin Name	Signal Name	Second Function	Type (See Table 2)	Description
C1, C2, C3, C4,	VSS_A1,			
D1, D2, D3, D4,	VSS_A2		Vee	Connect together
C8, C9, C10, C11,	VSS_B1		VSS	Connect together
D8, D9, D10, D11	VSS_B2			

Table 2: Pin Type Definition

Pin Type	Description	Pin Type	Description
DI	Digital Input	Al	Analogue Input
DO	Digital Output	AO	Analogue Output
DIO	Digital Input/Output	AIO	Analogue Input/Output
PS	Power Supply	VSS	Ground



3 Absolute Maximum Ratings

Table 3: Absolute Maximum Ratings

Parameter	Description	Conditions (Note 1)	Min	Тур	Max	Unit
T _{STG}	Storage temperature		-65		+150	°C
TJ	Junction temperature		-40		+150	°C
V_{DD_LIM}	Limiting supply voltage		-0.3		6.0	V
V _{PIN}	Limiting voltage at all pins except above		-0.3		V _{DD} + 0.3 (max 6.0)	V
Vesd_HBM	Electrostatic discharge voltage	Human Body Model			2	kV

Note 1 Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, so functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

4 Recommended Operating Conditions

Table 4: Recommended Operating Conditions

Parameter	Description	Conditions (Note 1)	Min	Тур	Max	Unit
V_{DD}	Supply voltage		2.8		5.5	V
T _{J_OP}	Operating junction temperature		-40		125	°C
TA	Ambient temperature		-40		105	ô
V _{DDIO}	Input/output supply voltage		1.2		3.6 (Note 2)	V
Ртот	Total power dissipation (Note 3)	TFBGA 0.8 mm pitch Derating factor above T _A = 70 °C: 29.3 mW/°C		1620		mW
θја	Thermal resistance junction to ambient (Note 3)	TFBGA 0.8 mm pitch		34.2		°C/W

Note 1 Within the specified limits, a lifetime of 10 years is guaranteed. If operating outside of these recommended conditions, please consult with Dialog Semiconductor.

Note 3 Obtained from measurement on a 6-layer evaluation board. Influenced by PCB technology and layout.

Note 2 V_{DDIO} is not allowed to be higher than V_{DD} .



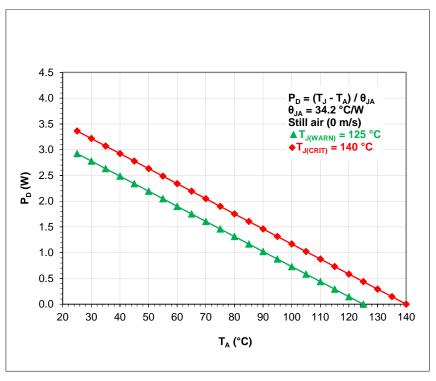


Figure 4: 66 TFBGA 0.8 mm Pitch Power Derating Curve



5 Electrical Characteristics

Unless otherwise noted, the following is valid for $T_J = -40$ to +125 °C, $V_{DD} = 2.8$ V to 5.5 V, $C_{OUT} = 47$ µF per phase, local sensing.

Table 5: Buck Converters Characteristics

Parameter	Description	Conditions	Min	Тур	Max	Unit
External Co	omponent Electrical Condition	S				
Соит	Output capacitance (per phase)	Including voltage and temperature coefficient	23	47	62	μF
ESRcout	Equivalent series resistance (per phase)	f > 100 kHz			10	mΩ
LPHASE	Inductance (per phase)	Including current and temperature dependence	0.11	0.22	0.29	μH
DCR _{LPHASE}	Inductor resistance				100	mΩ
Electrical C	haracteristics				•	
V_{DD}	Supply voltage	VDD_x = VSYS	2.8		5.5	V
V _{BUCK}	Buck output voltage (Note 1)	$I_O = 0$ to I_{O_MAX}	0.3		1.57	V
		Incl. static line/load reg and voltage ripple V _{BUCK} ≥ 1 V	-2.0		+2.0	%
VOACC	Output voltage accuracy PWM mode	Incl. static line/load reg and voltage ripple VBUCK < 1 V		±20		mV
		$V_{BUCK} = 1 \text{ V}$ $V_{DD} = 3.8 \text{ V}$ no load	-1.0		+1.0	%
		$V_{BUCK} = 1 \text{ V}$ $V_{DD} = 3.8 \text{ V}$ no load $T_A = 27 ^{\circ}\text{C}$	-0.5		+0.5	%
Vtr_load	Load regulation transient voltage (Note 2)	DA9223-A $I_{O} = 0$ to 5 A, tr = 500 ns PWM 4-phase $V_{BUCK} \ge 1$ V $V_{BUCK} < 1$ V DA9223-A IO = 0 to 5 A, tr = 500 ns		±2 ±20		% mV
		auto mode, ph shedding VBUCK = 1 V		±3.5		%
	Load regulation transient voltage (Note 2)	DA9224-A $I_O = 0$ to 5 A, tr = 500 ns PWM 2-phase $V_{BUCK} = 1$ V		±3.5		%
V _{TR_LINE}	Line regulation transient voltage	$V_{DD} = 3 \text{ to.} 3.6 \text{ V}$ $dt = 10 \mu\text{s}$ $I_{O} = IO(MAX)/2$		15		mV



Parameter	Description	Conditions	Min	Тур	Max	Unit
Io_max	Maximum output current	Per phase	4000			mA
ILIM_MIN	Minimum current limit per phase (programmable) (Note 3)	BUCKA_ILIM BUCKB_ILIM = 0000	-20%	4000	20%	mA
ILIM_MAX	Maximum current limit per phase (programmable) (Note 3)	BUCKA_ILIM BUCKB_ILIM = 1111	-20%	7000	20%	mA
I _{Q_PWM}	Quiescent current synchronous rectification mode	Per phase No load V _{DD} = 3.7 V		17		mA
fsw	Switching frequency			3		MHz
tsтир	Startup time	V _{OUT} = 1.0 V BUCKA_UP_CTRL BUCKB_UP_CTRL = 100		50 (Note 4)		μs
R _{O_PD}	Output pull-down resistance	For each phase at the LX node at 0.5 V, (see BUCKx_PD_DIS)		150	200	Ω
Ron_pmos	PMOS on-resistance	Incl. pin and routing VDD = 3.7 V per phase		29		mΩ
Ron_nmos	NMOS on-resistance	Incl. pin and routing V _{DD} = 3.7 V per phase		21		mΩ
PFM Mode			l	•		
V _{BUCK_PFM}	Buck output voltage in PFM	$I_O = 0$ mA to I_{O_MAX}	0.3		1.57	V
I _{MIN_PFM}	Minimum output current in PFM	Static output voltage, no DVC	2			mA
I _{Q_PFM_A2}	DA9224-A quiescent current Buck A enabled	No switching V _{DD} = 3.7 V (Note 5)		58		μA
IQ_PFM_A4	DA9223-A quiescent current Buck enabled	No switching V _{DD} = 3.7 V (Note 5)		72		μΑ
Iq_pfm_a2b2	DA9224-A quiescent current Buck A enabled Buck B enabled	No switching V _{DD} = 3.7 V (Note 5)		106		μΑ

Note 1 Programmable in 10 mV increments.

Note 2 Additional to the dc accuracy. Inductor value 0.22 uH. The value is measured directly at C_{OUT(EXT)}. In case of remote sensing, parasitics of PCB and external components may affect this value.



Note 3 On-time > 50 ns.

Note 4 Time from beginning to end of the voltage ramp. Additional 10 μs typical delay, plus internal sync to the enable port.

Note 5 For the total quiescent current of the IC, the I_{DD_ON} should be added.

Table 6: IC Performance and Supervision

Parameter	Description	Conditions	Min	Тур	Max	Unit
I _{DD_OFF}	Off state supply current	IC_EN = 0 T _A = 27 °C		0.1	1	μΑ
IDD_ON	On state supply current	IC_EN = 1 Buck A/B off T _A = 27 °C		14		μΑ
V _{TH_PG}	Power good threshold voltage	referred to VBUCK		-50		mV
V _H YS_PG	Power good hysteresis voltage			50		mV
VTH UVLO VDD	Under voltage lockout	BUCK_EN = 0		2.0	2.0	V
VIH_UVLO_VDD	threshold at VDD	BUCK_EN = 1		2.55		V
VTH_UVLO_IO	Under voltage lockout threshold at VDDIO		1.315	1.45	1.55	V
VHYS_UVLO_IO	Under voltage lockout hysteresis at VDDIO			70		mV
T _{TH_WARN}	Thermal warning threshold temperature		110	125	140	°C
T _{TH_CRIT}	Thermal critical threshold temperature		125	140	155	°C
T _{TH_POR}	Thermal power on reset threshold temperature		135	150	165	°C
fosc	Internal oscillator frequency		-7%	6.0	+7%	MHz



Table 7: Digital I/O Characteristics

Parameter	Description	Conditions	Min	Тур	Max	Unit
$V_{\text{IH_EN}}$	HIGH level input voltage at pin IC_EN		1.1			٧
V _{IL_EN}	LOW level input voltage at pin IC_EN				0.35	٧
t _{EN}	Enable time	I/F operating		750		μs
R _{O_PU_GPO}	Pull up resistor at GPO	$V_{DDIO} = 1.8 \text{ V}$ $V_{GPO} = 0 \text{ V}$		100		kΩ
R _{I_PD_GPI}	Pull down resistor at GPI	V _{DDIO} = 1.8 V V _{GPI} = VDDIO		150		kΩ
V _{IH}	GPI0-4, SCL, SDA, (2-WIRE mode) HIGH level input voltage	VDDCORE mode VDDIO mode	1.75 0.7*V _{DDIO}			V
V _{IL}	GPI0-4, SCL, SDA, (2-WIRE mode) LOW level input voltage	VDDCORE mode VDDIO mode			0.75 0.3*V _{DDIO}	V
Vih_4wire	SK, nCS, SI (4-WIRE Mode) HIGH level input voltage		0.7*V _{DDIO}			V
VIL_4WIRE	SK, nCS, SI (4-WIRE Mode) LOW level input voltage				0.3*V _{DDIO}	V
Vон	GPO2-3, SO (4-WIRE mode) HIGH level output voltage	push-pull mode at 1 mA V _{DDIO} ≥ 1.5 V	0.8*V _{DDIO}			V
V _{OL1}	GPO2-3, SDA (2-WIRE mode) SO (4-WIRE mode) LOW level output voltage at I _{OL} = 1 mA				0.3	V
V _{OL3}	SDA (2-WIRE Mode) LOW level output voltage at IoL = 3 mA				0.24	V
V _{OL20}	SDA (2-WIRE Mode) LOW level output voltage at IoL = 20 mA				0.4	V
CIN	CLK, SDA (2-WIRE Mode) input capacitance			2.5	10	pF
tsp	CLK, SDA (2-WIRE Mode) spike suppression pulse width	Fast/Fast+ mode High Speed mode	0		50 10	ns



Parameter	Description	Conditions	Min	Тур	Max	Unit
t _{fDA}	Fall time of SDA signal (2-WIRE Mode)	Fast at $C_B < 550$ pF HS at $10 < C_B < 100$ pF HS at $C_B < 400$ pF	20+0.1 C _B 10 20		120 80 160	ns

Table 8: 2-WIRE Control Bus Characteristics

Parameter	Description	Conditions	Min	Тур	Max	Unit
tBUF	Bus free time from STOP to START condition		0.5			μs
Св	Bus line capacitive load				150	pF
Standard/Fa	st/Fast+ Mode					
f _{SCL}	Clock frequency at pin SCL		0 (Note 1)		1000	kHz
t _{SU_STA}	START condition set- up time		0.26			μs
th_sta	START condition hold time		0.26			μs
tw_cl	Clock LOW duration		0.5			μs
tw_ch	Clock HIGH duration		0.26			μs
t _R	Rise time at pin CLK and DATA	Input requirement			1000	ns
tr	Fall time at pin CLK and DATA	Input requirement			300	ns
tsu_D	Data set-up time		50			ns
t _{H_D}	Data hold time		0			ns
High Speed	Mode					
f _{SCL_HS}	Clock frequency at pin SCL		0 (Note 1)		3400	kHz
tsu_sta_hs	START condition set- up time		160			ns
th_sta_hs	START condition hold time		160			ns
tw_cl_Hs	Clock LOW duration		160			ns
tw_ch_hs	Clock HIGH duration		60			ns
t _{R_HS}	Rise time at pin CLK and DATA	Input requirement			160	ns
t _{F_HS}	Fall time at pin CLK and DATA	Input requirement			160	ns
tsu_D_HS	Data set-up time		10			ns
t _{H_D_HS}	Data hold time		0			ns
t _{SU_STO_HS}	STOP condition set- up time		160			ns

Note 1 Minimum clock frequency is 10 kHz if 2WIRE_TO is enabled.



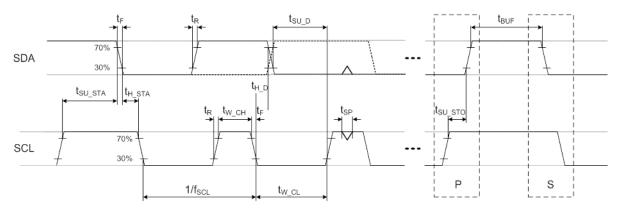


Figure 5: 2-WIRE Bus Timing

Table 9: 4-WIRE Control Bus Characteristics

Parameter	Description	Label in Plot	Min	Тур	Max	Unit
Св	Bus line capacitive load				100	pF
tc	Cycle time	1	70			ns
tsu_cs	Chip select setup time	2, from CS active to first SK edge	20			ns
t _{H_CS}	Chip select hold time	3, from last SK edge to CS idle	20			ns
tw_cl	Clock LOW duration	4	0.4 x tc			ns
tw_ch	Clock HIGH duration	5	0.4 x tc			ns
tsu_sı	Data input setup time	6	10			ns
th_si	Data input hold time	7	10			ns
tv_so	Data output valid time	8			22	ns
t _{H_} so	Data output hold time	9	6			ns
tw_cs	Chip select HIGH duration	10	20			ns



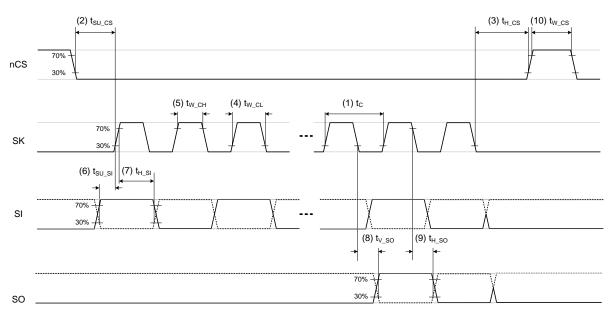


Figure 6: 4-WIRE Bus Timing



6 Efficiency Measurements

The efficiency measurements for DA9223-A and DA9224-A (in TFBGA 0.8 mm pitch package) are shown with phase shedding enabled in each plot and were measured using 2520 size inductor with typ. 8 m Ω DCR.

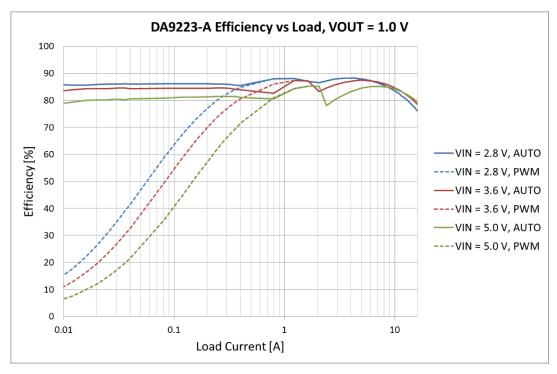


Figure 7: DA9223-A Efficiency vs Load, Vout = 1.0 V, 0-16 A

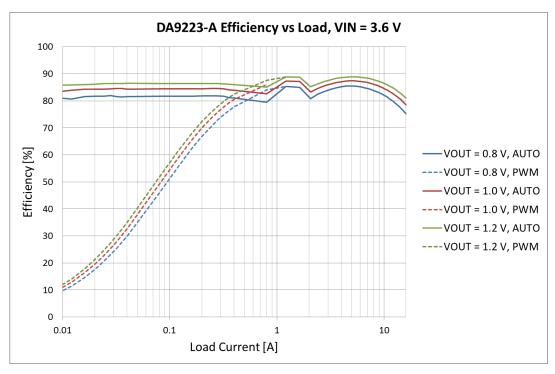


Figure 8: DA9223-A Efficiency vs Load, V_{IN} = 3.6 V, 0-16 A



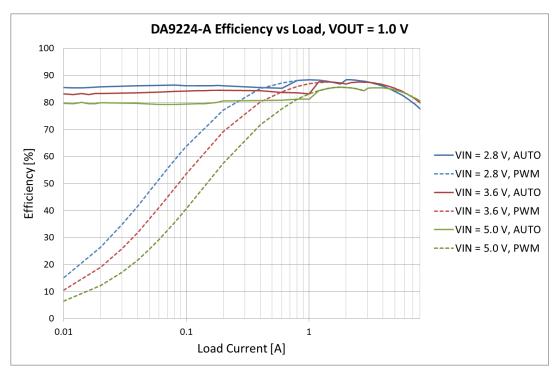


Figure 9: DA9224-A Efficiency vs Load, Vout = 1.0 V, 0-8 A

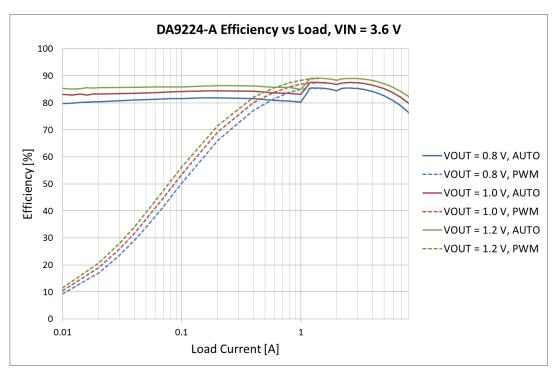


Figure 10: DA9224-A Efficiency vs Load, V_{IN} = 3.6 V, 0-8 A



7 Functional Description

Flexible configurability and the availability of different control schemes make both DA9223-A and DA9224-A the ideal single/dual buck companion ICs to expand the existing capabilities of a system PMIC such as DA9063.

Due to the advanced compatibility between both DA9223-A and DA9224-A and the DA9063, they offer several advantages when they are operated together. These advantages include:

- DA9223-A and DA9224-A can be enabled and controlled by DA9063 during the power up sequence, thanks to DA9063's dedicated output signals during power-up, and compatible input controls in both DA9223-A and DA9224-A.
- DA9223-A and DA9224-A can be used in a completely transparent way for the host processor and can share the same Control Interface (same SPI chip select or I²C address), thanks to the compatible registers map. DA9223-A and DA9224-A have a dedicated register space for configuration and control which doesn't conflict with DA9063.
- DA9223-A and DA9224-A support a power-good configurable port for enhanced communication to the host processor and improved power-up sequencing.
- DA9223-A and DA9224-A can both share the same interrupt line with DA9063.

In addition, the 2-WIRE / 4-WIRE interfaces allow DA9223-A and DA9224-A to fit to many standard PMU parts and power applications.

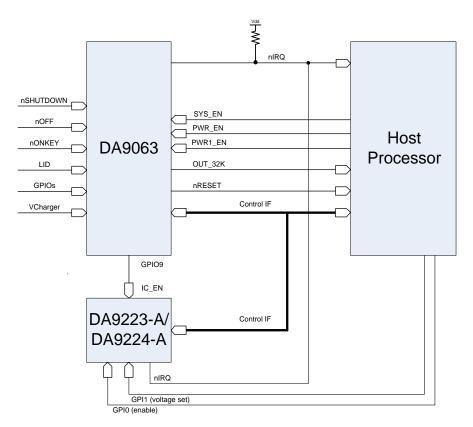


Figure 11: Interface of DA9223-A/24-A with DA9063 and the Host Processor

As shown in Figure 11, a typical application case includes a host processor, a main PMIC (for example, DA9063) and DA9223-A or DA9224-A used as companion IC for the high power core supply.

The easiest way of controlling DA9223-A and DA9224-A is through the Control Interface. The master initiating the communication must always be the host processor that reads and writes to the main PMIC, and to the DA9223-A and DA9224-A registers. To poll the status of DA9223-A or DA9224-A,



the host processor must access the dedicated register area through the Control Interface. DA9223-A and DA9224-A can additionally be controlled by means of hardware inputs.

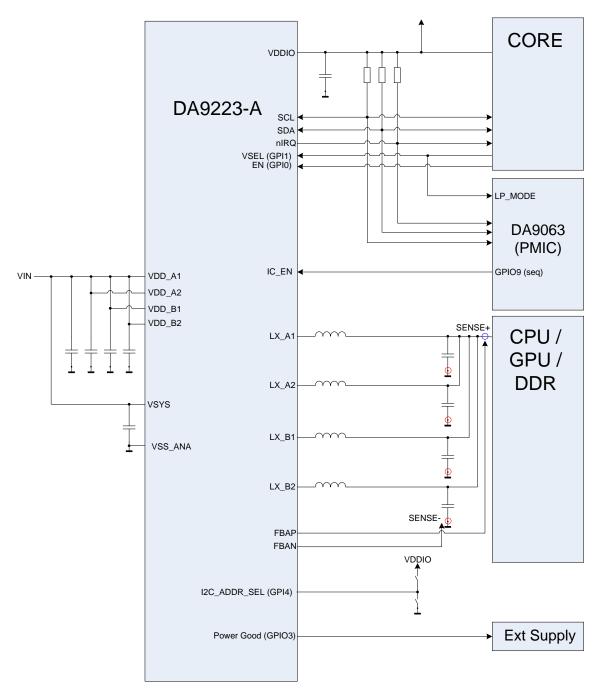


Figure 12: Typical Application of DA9223-A

Figure 12 shows a typical use case of DA9223-A for the supply of CPU, GPU, or DDR rails. The IC is enabled and disabled by the main PMIC via IC_EN port as part of its sequencer. Once the IC is enabled, the CORE application processor enables the buck converter with the EN1 signal and manages the output voltage selection with the VSEL signal.

The VSEL signal can be shared between the main PMIC and the DA9223-A. Three GPI/GPIOs embedded in DA9223-A are used in this case:

• GPIO2 signals the insertion of an external charger in the application (through interrupt to the host processor)



- GPIO3 indicates a power-good-condition, either to proceed with the power up sequence or to enable an external supply connected to the port
- GPI4 is used for the I²C interface address hardware selection

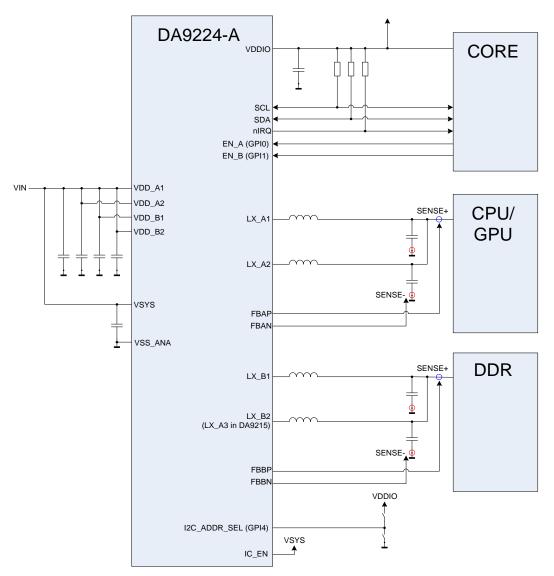


Figure 13: Typical Application of DA9224-A

Figure 13 shows a typical use case of DA9224-A for the simultaneous supply of a CPU and a GPU rail. The IC is always enabled because IC_EN is shorted to the battery voltage. The CORE application processor enables and disables the CPU/GPU and the DDR individually via dedicated ports on DA9224-A.

7.1 DC-DC Buck Converter

DA9223-A is a four-phase 16 A high efficiency synchronous step-down DVC regulator, operating at a high frequency of typically 3 MHz. It supplies an output voltage of typically 1.0 V for a CPU rail, configurable in the range 0.3 – 1.57 V, with high accuracy in steps of 10 mV.

DA9224-A contains two buck converters, Buck A and Buck B, each capable of delivering 8 A.

To improve the accuracy of the delivered voltage, each buck converter can support a differential se nsing of the configured voltage directly at the point of load via dedicated positive and negative sense pins.



Both Buck A and Buck B have two voltage registers each. One defines the normal output voltage, while the other offers an alternative retention voltage. In this way different application power modes can easily be supported. The voltage selection can be operated either via GPI or via control interface to guarantee the maximum flexibility according to the specific host processor status in the application.

When a buck is enabled, its output voltage is monitored and a power-good signal indicates that the buck output voltage has reached a level higher than the VTH(PG) threshold. The power-good is lost when the voltage drops below VTH(PG) - VHYS(PG), which is the level at which the signal is deasserted. The power good signaling should not be used in conjunction with fast start up rates, configured in BUCKx_UP_CTRL register fields and can be individually masked during DVC transitions using the PGA_DVC_MASK and PGB_DVC_MASK bits. For each of the buck converters the status of the power-good indicator can be read back via I²C from the PWRGOOD_A and PWRGOOD_B status bits. It can be also individually assigned to either GPIO2 or GPIO3 using BUCKA_PG_SEL and BUCKB_PG_SEL. For correct functionality, the GPIO ports need to be configured as output. An I²C write in GPIOx_MODE can overwrite the internal configuration so that a new update will be automatically done only when the internal power-good indicator changes status.

The buck converters are capable of supporting DVC transitions that occur:

- When they are active and the selected A-voltage or B-voltage is updated to a new target value.
- When the voltage selection is changed from the A-voltage to the B-voltage (or B-voltage to the A-voltage) using VBUCKA_SEL and VBUCKB_SEL.

The DVC controller operates in Pulse Width Modulation (PWM) mode with synchronous rectification. When the host processor changes the output voltage, the voltage transition of each buck converter can be individually signaled with a READY signal routed to either GPIO2 or GPIO3. The port has to be configured as GPO and selected for the functionality via READYA_CONF or READYB_CONF. In contrast to the power-good signal, the READY only informs the host processor about the completion of the digital DVC ramp without confirming that the target voltage has actually been reached.

The slew rate of the DVC transition is individually programmed for each buck converter at 10mV per (4, 2, 1 or 0.5 µs) via control bit SLEW RATE A and SLEW RATE B.

The typical supply current in PWM mode is in the order of 17 mA per phase (quiescent current and charge/discharge current) and drops to <1 µA when the buck is turned off.

When the buck is disabled, a pull-down resistor (typically 150 Ω) for each phase is activated depending on the value stored in register bits BUCKA_PD_DIS and BUCKB_PD_DIS. Phases disabled using PHASE_SEL_A and PHASE_SEL_B will not have any pull-down. The pull-down resistor is always disabled at all phases when DA9223-A and DA9224-A are OFF.

7.1.1 Switching Frequency

The switching frequency is chosen to be high enough to allow the use of a small 0.22 μ H inductor (see a complete list of coils in the Application Information, Section 9). The buck switching frequency can be tuned using register bit OSC_TUNE. The internal 6 MHz oscillator frequency is tuned in steps of 180 kHz. This impacts the buck converter frequency in steps of 90 kHz and helps to mitigate possible disturbances to other HF systems in the application.

7.1.2 Operation Modes and Phase Selection

The buck converters can operate in synchronous PWM mode and PFM mode. The operating mode is selected using register bits BUCKA_MODE and BUCKB_MODE.

An automatic phase shedding can be enabled for each buck converter in PWM mode via EF PH_SH_EN_A \h * MERGEFORMAT PH_SH_EN_A, PH_SH_EN_B, thereby automatically reducing or increasing the number of active phases depending on the output load current. For DA9224-A the phase shedding will automatically change between 1-phase and 2-phase operation at a typical current of 2.0 A. For DA9223-A the phase shedding will automatically change between 1-phase and 4-phase operation at a typical current of 2.5 A. The PHASE_SEL_A and PHASE_SEL_B register fields limit the maximum number of active phases under any conditions.



If the automatic operation mode is selected on BUCKA_MODE or BUCKB_MODE, the buck converters will automatically change between synchronous PWM mode and PFM depending on the load current. This improves the efficiency of the converters across the whole range of output load currents.

7.1.3 Output Voltage Selection

The switching converter can be configured using either a 2-WIRE or a 4-WIRE interface. For security reasons, the re-programming of registers that can cause damage when wrongly programmed (for example, the voltage settings) can be disabled by asserting the control V_LOCK. When V_LOCK is asserted, reprogramming the registers 0xD0 to 0x14F from control interfaces is disabled.

For each buck converter two output voltages can be pre-configured inside registers VBUCKA_A and VBUCKB_A, and registers VBUCKA_B and VBUCKB_B. The output voltage can be selected by either toggling register bits VBUCKA_SEL and VBUCKB_SEL or by re-programming the selected voltage control register. Both changes will result in ramped voltage transitions, during which the READY signal is asserted. After being enabled, the buck converter will by default use the register settings in VBUCKA_A and VBUCKB_A unless the output voltage selection is configured via the GPI port.

If "00" has been selected in BUCKA_MODE or BUCKB_MODE, A-/B- voltage selection registers VBUCKx_x control the operation of the PWM and PFM modes.

Regardless of the values programmed in the VBUCKx_A and VBUCKx_B registers, the registers VBUCKA_MAX, VBUCKB_MAX will individually limit the maximum output voltage that can be set for each of the buck converters.

The buck converter provides an optional hardware enable/disable via selectable GPI, and configured via control register bits BUCKA_GPI and BUCKB_GPI. A change of the output voltage controlled by the state of a GPI is enabled via control register bits VBUCKA_GPI and VBUCKB_GPI. A rising or falling edge at the related GPI, DA9223-A and DA9224-A will configure the buck converters according to the status of the GPI.

In addition to selecting between the A/B voltages, a track mode can be activated for Buck A to set the output voltage. In the DA9223-A, the track mode is applied to the 4-phase buck converter. This feature can be enabled on GPI0 via GPI0_PIN. The output voltage will be configured to follow the voltage applied at a selected GPI pin. The voltage applied at GPI0 must be in the same range as the nominal output voltage selectable for the buck rail (see VBUCKA_A and VBUCKA_B registers). In Track Mode, only single ended remote sensing is possible.

In Track Mode, the content of the VBUCKA_SEL bit is ignored, as well as VBUCKA_A and VBUCKA_B bits. They will become active again once the voltage track mode is disabled. The GPI0 does not generate any event in this case.

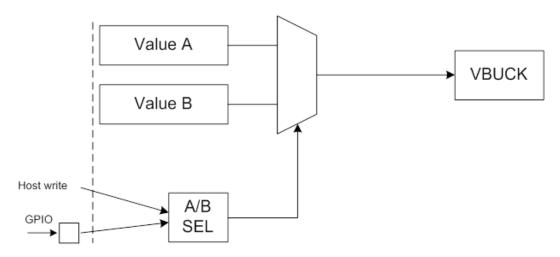


Figure 14: Concept of Control of the Buck's Output Voltage



7.1.4 Soft Start Up

To limit in-rush current from VSYS, the buck converters can perform a soft-start after being enabled. The start-up behavior is a compromise between acceptable inrush current from the battery and turn-on time. In DA9223-A and DA9224-A different ramp times can be individually configured for each buck converter on register BUCKA_UP_CTRL and BUCKB_UP_CTRL. Rates higher than 20 mV/µs may produce overshoot during the start-up phase, so they should be considered carefully. It is also recommended to place a decoupling capacitor on the feedback lines if slow ramp-up slew rate; slower than 2.5 mV/µs is used.

A ramped power-down can be selected on register bits BUCKA_DOWN_CTRL and BUCKB_DOWN_CTRL. When no ramp is selected, the output node will only be discharged by the pull-down resistor, if enabled via BUCKA_PD_DIS and BUCKB_PD_DIS.

7.1.5 Current Limit

The integrated current limit is meant to protect DA9223-A and DA9224-A power stages and the external coil from excessive current. The bucks' current limit should be configured to be at least 40% higher than the required maximum continuous output current.

When reaching the current limit, each buck converter generates an event and an interrupt to the host processor unless the interrupt has been masked using the OCx_MASK controls. These OCA_MASK and OCB_MASK control bits can be used to mask the generation of over-current events during DVC transitions. An extra masking time as defined in OCx_MASK will be automatically added to the DVC interval after the DVC has finished in order to ensure that the possible high current levels needed for DVC do not influence the event generation.

7.1.6 Variable VOUT above 1.57 V

The whole product family is also available with an adjustable output voltage up to 4.3V. A resistive divider from VOUT to FBAN (or FBBN) can be used to set the output voltage higher than 1.57 V, see Figure 15.

The value of the output voltage VOUT is set by the selection of the resistive divider shown in equation 1. The total resistance of the divider resistors (R1+R2) should be less than 40 k Ω .

$$VOUT = \left(1 + \frac{R1}{R2}\right) \cdot VREF$$

Equation 1

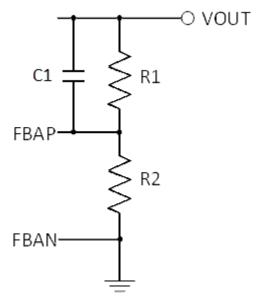


Figure 15: Resistive Divider from VOUT to FBAN

DA9223-A and DA9224-A



Auto Grade 0.8 mm Pitch Multi-Phase Buck Converter

For example, to program the output voltage VOUT to 1.8 V, with VREF set to 1.2 V, suggest 10 k Ω on R1 and 20 k Ω on R2.

- Note 1 The resistors need to be properly selected since the output voltage accuracy will be directly affected by any errors on the resistors. The voltage across FBAP and FBAN (VREF) is guaranteed, but not the output voltage accuracy.
- Note 2 For best accuracy and tracking R1 = R2 and VREF is adjusted to be 1/2 x Vout.
- **Note 3** Capacitor C1 is used to provide feed forward control to improve transient response. The value of C1 should be between 1 nF and 10 nF.

<u>^</u>

CAUTION

The followings are important notes that need to be considered before using resistive divider on DA9223-A and DA9224-A:

- Please contact your region's Dialog representative when adopting the resistive divider technique. Dialog need to prepare a special OTP because incorrect OTP settings may result in a different output voltage than expected.
- The voltage difference between input voltage and output voltage needs to be: above 1.2 V, VIN-VOUT > 1.2 V.
- 3. The total resistance (R1+R2) is less than 40 k Ω .
- 4. It is recommended that the device is operated in PWM mode only.

© 2022 Renesas Electronics



7.2 Ports Description

This section describes the functionality of each input / output port.

7.2.1 VDDIO

VDDIO is an independent IO supply rail input to DA9223-A and DA9224-A that can be assigned to the power manager interface and to the GPIOs (see control PM_IF_V and GPI_V). The rail assignment determines the IO voltage levels and logical thresholds (see also the Digital I/O Characteristics in Table 7).

An integrated under voltage lockout circuit for the VDDIO prevents internal errors by disabling the I²C communication when the voltage drops below VULO_IO. In that case the buck converters are also disabled and cannot be re-enabled (even via input port) until the VDDIO under-voltage condition has been resolved. At the exit of the VDDIO under voltage condition an event E_UVLO_IO is generated and the nIRQ line is driven active if the event is not masked.

The VDDIO under-voltage circuit monitors voltages relative to a nominal voltage of 1.8V. If a different rail voltage is being used, the under-voltage circuit can be disabled via UVLO IO DIS.

Note that the maximum speed at 4-WIRE interface is only available if the selected supply rail is greater than 1.6 V.

7.2.2 IC EN

IC_EN is a general enable signal for DA9223-A and DA9224-A turning on and off the internal circuitry (for example, the reference, the digital core, etc.). Correct control of this port has a direct impact on the quiescent current of the whole application. A low level of IC_EN allows the device to reach the minimum quiescent current. The voltage at this pin is continuously sensed by a dedicated analogue circuit.

The host processor can begin to start communication with DA9223-A and DA9224-A through the Control Interface and, for example to turn on the buck converters, a delay time of ten after assertion of the IC_EN pin. If the bucks are enabled via OTP (see BUCKA_EN and BUCKB_EN controls), they will start up automatically after assertion of IC_EN.

The IC_EN activation threshold is defined with a built-in hysteresis to avoid glitching transitions that take place with unstable rising or falling edges.

7.2.3 nIRQ

The nIRQ port indicates that an interrupt-causing event has occurred and that the event/status information is available in the related registers. The nIRQ is an output signal that can either be push-pull or open drain (selected via IRQ_TYPE). If an active high IRQ signal is required, it can be achieved by asserting control IRQ_LEVEL (recommended for push-pull mode).

Examples of this type of information can be critical temperature and voltage, fault conditions, status changes at GPI ports, and so forth. The event registers hold information about the events that have occurred. Events are triggered by a status change at the monitored signals. When an event bit is set, the nIRQ signal is asserted unless this interrupt is masked by a bit in the IRQ mask register. The nIRQ will not be released until all event registers with asserted bits have been read and cleared. New events that occur during reading an event register are held until the event register has been cleared, ensuring that the host processor does not miss them.



7.2.4 GPIO Extender

DA9223-A and DA9224-A include a GPIO extender that offers up to five 5 V-tolerant general purpose input/output ports. Each port is controlled via registers from the host processor.

The GPIO3 and GPI4 ports are pin-shared with the 4-WIRE Control Interface. For instance, if GPIO3_PIN = 01, GPI4_PIN = 01 (Interface selected), the GPIO3 and GPI4 ports will be exclusively dedicated to output and chip-select signaling for 4-WIRE purposes. If the alternative function is selected, all GPIOs configuration as per registers 0x58 to 0x5A and 0x145 will be ignored.

GPIs are supplied from the internal rail VDDCORE or VDDIO (selected via GPI_V) and can be configured to be active high or active low (selected via GPIOx_TYPE). The input signals can be debounced or immediately change the state of the assigned status register GPIx to high or low, according to the setting of GPIOx_MODE. The debouncing time is configurable via control DEBOUNCE (10 ms default).

Whenever the status has changed to its configured active state (edge sensitive), the assigned event register is set and the nIRQ signal is asserted (unless this nIRQ is masked, see also Figure 16).

Whenever DA9223-A and DA9224-A is enabled and enters ON mode (also when enabled changing the setting of GPIOx_PIN) the GPI status bits are initiated towards their configured passive state. This ensures that already active signals are detected, and that they create an event immediately after the GPI comparators are enabled.

The buck enable signal (BUCKx_EN) can be controlled directly via a GPI, if so configured in the BUCKA_GPI and BUCKB_GPI registers. If it is required that GPI ports do not generate an event when configured for the HW control of the switching regulator, the relative mask bit should be set.

GPIs can alternatively be selected to toggle the VBUCKA_SEL and VBUCKB_SEL from rising and falling edges at these inputs. Apart from changing the regulator output voltage this also provides hardware control of the regulator mode (normal/low power mode) from the settings of BUCKA_SL_A, BUCKA_SL_B, BUCKB_SL_A, and BUCKB_SL_B (enabled if BUCKA_MODE or BUCKB_MODE = '00').

All GPI ports have the additional option of activating a 100 k Ω pull-down resistor via GPIOx_PUPD, which ensures a well-defined level in case the input is not actively driven.

If enabled via ADDR_SEL_CONF, the I²C address selection can be assigned to a specific GPI. An active voltage level at the selected GPI configures the slave address of DA9223-A and DA9224-A to IF_BASE_ADDR1 while a passive voltage level configures the slave address to IF_BASE_ADDR2. If no GPI is selected then the IF_BASE_ADDR1 is automatically used.

If defined as an output, GPIOs can be configured to be open-drain or push-pull. If configured as push-pull, the supply rail is VDDIO. By disabling the internal 120 k Ω pull-up resistor in open-drain mode, the GPO can also be supplied from an external rail. The output state will be assigned as configured by the GPIO register bit GPIOx_MODE.

A specific power-good port for each of the buck converters can be configured via BUCKA_PG_SEL and BUCKB_PG_SEL. The respective port must be configured as GPO for correct operation. If assigned to the same GPO, it is necessary that the power-good indicators for Buck A and Buck B are both active (supply voltages in range) to assert the overall power-good. The signal will be released as soon as one of the single power-good signals is not active (that is, at least one supply is out of range).

The power good signaling should not be used in conjunction with fast start up rates, configured in BUCKx_UP_CTRL register fields.

Once enabled via RELOAD_FUNC_EN the GPI0 can be used as input port to operate a partial OTP download. When the input level is changed to active, the registers 0x5D, 0x5E, 0xD1 to 0xDA are updated to their OTP default. This allows a complete buck re-configuration that resets all the changes done to those registers previously (soft reset). If the buck should be kept on during the soft reset, the OTP values for the enable bits should be asserted because they are also part of the reload.



Whenever the GPIO unit is off (POR or OFF Mode) all ports are configured as open drain active high (pass device switched off, high impedance state). When leaving POR the pull-up or pull-down resistors will be configured from register GPIOx_PUPD.

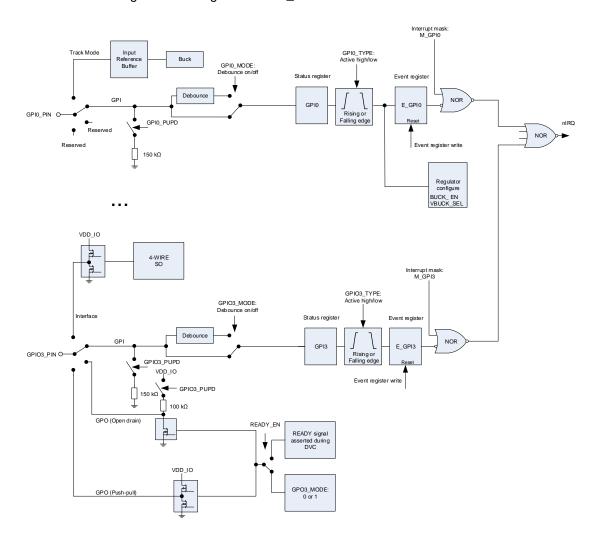


Figure 16: GPIO Principle of Operation (Example Paths)

DA9223-A and DA9224-A



Auto Grade 0.8 mm Pitch Multi-Phase Buck Converter

7.3 Operating Modes

7.3.1 ON Mode

DA9223-A and DA9224-A are in ON Mode when the IC_EN port is higher than EN_ON and the supply voltage is higher than $V_{TH(UVLO)(VDD)}$. Once enabled, the host processor can start the communication with DA9223-A and DA9224-A via Control Interface after the t_{EN} delay needed for internal circuit start up.

If BUCKA_EN or BUCKB_EN is asserted when DA9223-A and DA9224-A are in ON Mode the power up of the related buck converter is initiated. If the bucks are controlled via GPI, the level of the controlling ports is checked when entering ON mode, so that an active level will immediately have effect on the buck. If BUCKA_EN or BUCKB_EN are not asserted and all controlling GPI ports are inactive, the buck converter will stay off with the output pull-down resistor enabled/disabled according to the setting of BUCKA_PD_DIS and BUCKB_PD_DIS.

7.3.2 OFF Mode

DA9223-A and DA9224-A are in OFF Mode when the IC_EN port is lower than EN_OFF. In OFF Mode, the bucks are always disabled and the output pull-down resistors are disabled independently of BUCKA_PD_DIS and BUCKB_PD_DIS. All I/O ports of DA9223-A and DA9224-A are configured as high impedance.



7.4 Control Interfaces

All the features of DA9223-A and DA9224-A can be controlled by SW through a serial control interfaces. The communication is selectable to be either a 2-WIRE (I²C compliant) or a 4-WIRE connection (SPI compliant) via control IF_TYPE, which will be selected during the initial OTP read. If 4-WIRE is selected, the GPIO3 and GPI4 are automatically configured as interface pins. Data is shifted into or out of DA9223-A and DA9224-A under the control of the host processor, which also provides the serial clock. In a normal application case the interface is only configured once from OTP values, which are loaded during the initial start-up of DA9223-A and DA9224-A.

DA9223-A and DA9224-A react only on read/write commands where the transmitted register address (using the actual page bits as a MSB address range extensions) is within 0x50 to 0x67, 0xD0 to DF, 0x140 to 0x14F and (read only) 0x200 to 0x27F. Host access to registers outside these ranges will be ignored. This means there will be no acknowledge after receiving the register address in 2-WIRE Mode, and SO stays HI-Z in 4-WIRE Mode. During debug and production modes write access is available to page 4 (0x200 to 0x27F). DA9223-A and DA9224-A react only on write commands where the transmitted register address is 0x00, 0x80, 0x100 to0x106. The host processor must read the content of those registers before writing, thereby changing only the bit fields that are not marked as reserved (the content of the read back comes from the compatible PMIC, for example DA9063).

If the STAND_ALONE bit is asserted (OTP bit), DA9223-A and DA9224-A also react to read commands.

7.4.1 4-WIRE Communication

In 4-WIRE Mode the interface uses a chip-select line (nCS/nSS), a clock line (SK), data input (SI) and data output line (SO).

The DA9223-A and DA9224-A register map is split into four pages that each contain up to 128 registers. The register at address zero on each page is used as a page control register. The default active page after turn-on includes registers 0x50 to 0x6F. Writing to the page control register changes the active page for all subsequent read/write operations unless an automatic return to page 0 was selected by asserting bit REVERT. Unless the REVERT bit was asserted after modifying the active page, it is recommended to read back the page control register to ensure that future data exchange is accessing the intended registers.

All registers outside the DA9223-A and DA9224-A range are write only, that is, the DA9223-A and DA9224-A will not answer to a read command and the data bus is tri-state (they are implicitly directed to DA9063). In particular the information contained in registers 0x105 and 0x106 is used by DA9223-A and DA9224-A to configure the control interface. They must be the same as the main PMIC (DA9063), so that a write to those registers configures both the main PMIC and DA9223-A and DA9224-A at the same time. The default OTP settings also need to be identical for a correct operation of the system.

The 4-WIRE interface features a half-duplex operation, that is, data can be transmitted and received within a single 16-bit frame at enhanced clock speed (up to 14 MHz). It operates at the clock frequencies provided by the host.

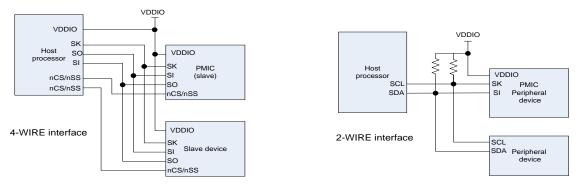


Figure 17: Schematic of 4-WIRE and 2-WIRE Power Manager Bus



A transmission begins when initiated by the host. Reading and writing is accomplished by the use of an 8-bit command, which is sent by the host prior to the exchanged 8-bit data. The byte from the host begins shifting in on the SI pin under the control of the serial clock SK provided from the host. The first seven bits specify the register address (0x01 to 0x07) that will be written or read by the host. The register address is automatically decoded after receiving the seventh address bit. The command word ends with an R/W bit, which together with the control bit R/W_POL specifies the direction of the following data exchange. During register writing the host continues sending out data during the following eight SK clocks. For reading, the host stops transmitting and the 8-bit register is clocked out of DA9223-A and DA9224-A during the consecutive eight SK clocks of the frame. Address and data are transmitted with MSB first. The polarity (active state) of nCS is defined by control bit nCS_POL. nCS resets the interface when inactive and it has to be released between successive cycles.

The SO output from DA9223-A and DA9224-A is normally in high-impedance state and active only during the second half of read cycles. A pull-up or pull-down resistor may be needed at the SO line if a floating logic signal can cause unintended current consumption inside other circuits.

Table 10: 4-WIRE Clock Configurations

Configurations				
CPHA Clock Polarity	CPOL Clock Phase	Output Data is Updated at SK Edge	Input Data is Registered at SK Edge	
0 (idle low)	0	Falling	Rising	
0 (idle low)	1	Rising	Falling	
1 (idle high)	0	Rising	Falling	
1 (idle high)	1	Falling	Rising	

DA9223-A and DA9224-A's 4-WIRE interface offers two further configuration bits. Clock polarity (CPOL) and clock phase (CPHA) define when the interface will latch the serial data bits. CPOL determines whether SK idles high (CPOL = 1) or low (CPOL = 0). CPHA determines on which SK edge data is shifted in and out. With CPOL = 0 and CPHA = 0, DA9223-A and DA9224-A latch data on the SK rising edge. If the CPHA is set to 1 the data is latched on the SK falling edge. CPOL and CPHA states allow four different combinations of clock polarity and phase. Each setting is incompatible with the other three. The host and DA9223-A and DA9224-A must be set to the same CPOL and CPHA states to communicate with each other.



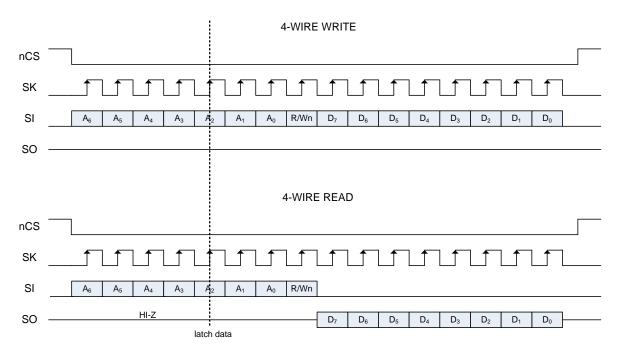


Figure 18: 4-WIRE Host Write and Read Timing (nCS_POL = '0', CPOL = '0', CPHA = '0')

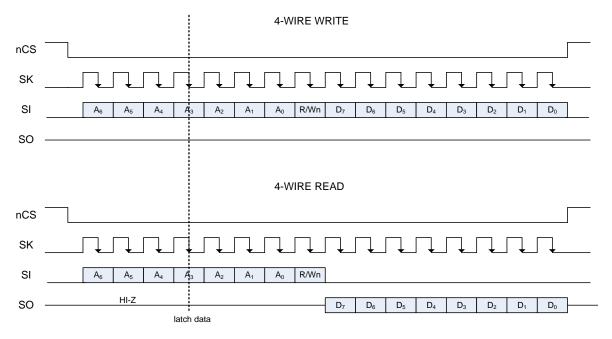


Figure 19: 4-WIRE Host Write and Read Timing (nCS_POL= '0', CPOL = '0', CPHA = '1')



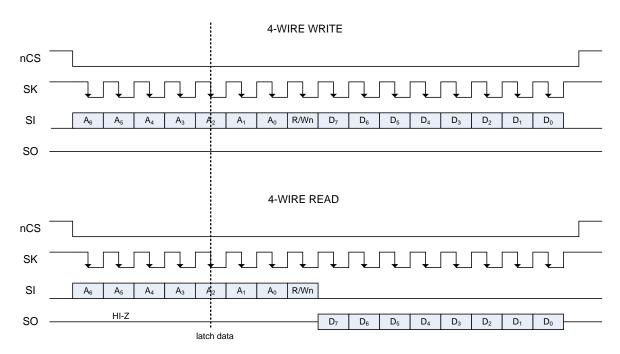


Figure 20: 4-WIRE Host Write and Read Timing (nCS_POL = '0', CPOL = '1', CPHA = '0')

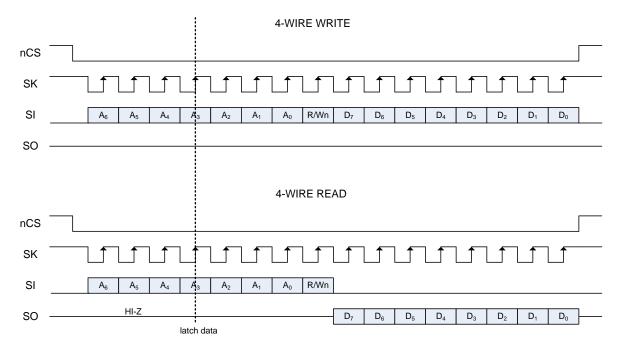


Figure 21: 4-WIRE Host Write and Read Timing (nCS_POL = '0', CPOL = '1', CPHA = '1')



Table 11: 4-WIRE Interface Summary

Parameters					
	nCS	Chip select			
Cignal Lines	SI Serial input data	Master out Slave in			
Signal Lines	SO Serial output data	Master in Slave out			
	SK	Transmission clock			
Interface	Push-pull with tristate				
Supply voltage	Selected from VDDIO	1.6 V to 3.3 V			
Data rate	Effective read/write data	Up to 7 Mbps			
Transmission	Half-duplex	MSB first			
Transmission	16 bit cycles	7-bit address, 1 bit read/write, 8-bit data			
	CPOL	Clock polarity			
Configuration	СРНА	Clock phase			
	nCS_POL	nCS is active low/high			

Note that reading the same register at high clock rates directly after writing it does not guarantee a correct value. It is recommended to keep a delay of one frame until re-accessing a register that has just been written (for example, by writing/reading another register address in between).

7.4.2 2-WIRE Communication

The IF_TYPE bit in the INTERFACE2 register can be used to configure the DA9223-A and DA9224-A control interface as a 2-WIRE serial data interface. In this case the GPIO3 and GPI4 are free for regular input/output functions. DA9223-A and DA9224-A has a configurable device write address (default: 0xD0) and a configurable device read address (default: 0xD1). See control IF_BASE_ADDR1 for details of configurable addresses. The ADDR_SEL_CONF bit is used to configure the device address as IF_BASE_ADDR1 or IF_BASE_ADDR2 depending on the voltage level applied at a configurable GPI port (see Section 7.2.4).

The SK port functions as the 2-WIRE clock and the SI port carries all the power manager bi-directional 2-WIRE data. The 2-WIRE interface is open-drain supporting multiple devices on a single line. The bus lines have to be pulled HIGH by external pull-up resistors (in the 2 k Ω to 20 k Ω range). The attached devices only drive the bus lines LOW by connecting them to ground. As a result two devices cannot conflict if they drive the bus simultaneously. In standard/fast mode the highest frequency of the bus is 400 kHz. The exact frequency can be determined by the application and does not have any relation to the DA9223-A and DA9224-A internal clock signals. DA9223-A and DA9224-A will follow the host clock speed within the described limitations, and does not initiate any clock arbitration or slow down. An automatic interface reset can be triggered using control 2WIRE_TO if the clock signal stops to toggle for more than 35 ms.

The interface supports operation compatible to Standard, Fast, Fast-Plus and High Speed mode of the I²C-bus specification Rev 4. Operation in high speed mode at 3.4 MHz requires mode changing in order to set spike suppression and slope control characteristics to be compatible with the I²C-bus specification. The high speed mode can be enabled on a transfer by transfer basis by sending the master code (0000 1XXX) at the beginning of the transfer. DA9223-A and DA9224-A do not make use of clock stretching, and deliver read data without additional delay up to 3.4 MHz.

Alternatively, PM_IF_HSM configures the interface to use high speed mode continuously. In this case, the master code is not required at the beginning of every transfer. This reduces the communication overhead on the bus but limits the slaves attachable to the bus to compatible devices.

The communication on the 2-WIRE bus always takes place between two devices, one acting as the master and the other as the slave. The DA9223-A and DA9224-A will only operate as a SLAVE.



In contrast to the 4-WIRE mode, the 2-WIRE interface has direct access to two pages of the register map (up to 256 addresses). The register at address zero on each page is used as a page control register (with the 2-WIRE bus ignoring the LSB of control REG_PAGE). Writing to the page control register changes the active page for all subsequent read/write operations unless an automatic return to page 0 was selected by asserting control REVERT. Unless REVERT was asserted after modifying the active page, it is recommended to read back the page control register to ensure that future data exchange is accessing the intended registers.

In 2-WIRE operation DA9223-A and DA9224-A offer an alternative way to access register page 2 and page 3. It removes the need for preceding page selection writes by incrementing the device write/read address by one (default 0xD2/0xD3) for any direct access of page 2 and page 3 (page 0 and 1 access requires the basic write/read device address with the MSB of REG_PAGE to be '0').

7.4.3 Details of the 2-WIRE Control Bus Protocol

All data is transmitted across the 2-WIRE bus in groups of eight bits. To send a bit the SDA line is driven towards the intended state while the SCL is LOW (a low on SDA indicates a zero bit). Once the SDA has settled, the SCL line is brought HIGH and then LOW. This pulse on SCL clocks the SDA bit into the receiver's shift register.

A two-byte serial protocol is used containing one byte for address and one byte data. Data and address transfer are transmitted MSB first for both read and write operations. All transmissions begin with the START condition from the master while the bus is in IDLE state (the bus is free). It is initiated by a high to low transition on the SDA line while the SCL is in the high state (a STOP condition is indicated by a low to high transition on the SDA line while the SCL is in the high state).



Figure 22: Timing of 2-WIRE START and STOP Condition

The 2-WIRE bus is monitored by DA9223-A and DA9224-A for a valid SLAVE address whenever the interface is enabled. It responds immediately when it receives its own slave address. The acknowledge is done by pulling the SDA line low during the following clock cycle (white blocks marked with 'A' in Figure 23 to Figure 27).

The protocol for a register write from master to slave consists of a start condition, a slave address with read/write bit and the 8-bit register address followed by eight bits of data terminated by a STOP condition. DA9223-A and DA9224-A respond to all bytes with Acknowledge. This is illustrated in Figure 23.

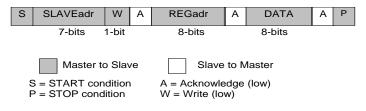


Figure 23: 2-WIRE Byte Write (SDA Line)



When the host reads data from a register it first has to write to DA9223-A and DA9224-A with the target register address and then read from DA9223-A and DA9224-A with a Repeated START or alternatively a second START condition. After receiving the data, the host sends No Acknowledge and terminates the transmission with a STOP condition. This is illustrated in Figure 24.

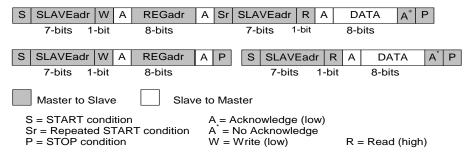


Figure 24: Examples of 2-WIRE Byte Read (SDA Line)

Consecutive (page) read out mode is initiated from the master by sending an Acknowledge instead of Not acknowledge after receipt of the data word. The 2-WIRE control block then increments the address pointer to the next 2-WIRE address and sends the data to the master. This enables an unlimited read of data bytes until the master sends a Not acknowledge directly after the receipt of data, followed by a subsequent STOP condition. If a non-existent 2-WIRE address is read out, the DA9223-A and DA9224-A will return code zero. This is illustrated in Figure 25.

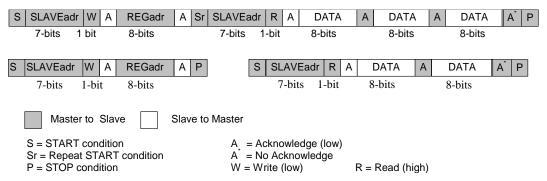


Figure 25: Examples of 2-WIRE Page Read (SDA Line)

Note that the slave address after the Repeated START condition must be the same as the previous slave address.

Consecutive (page) write mode is supported if the Master sends several data bytes following a slave register address. The 2-WIRE control block then increments the address pointer to the next 2-WIRE address, stores the received data and sends an Acknowledge until the master sends the STOP condition. This is illustrated in Figure 26.

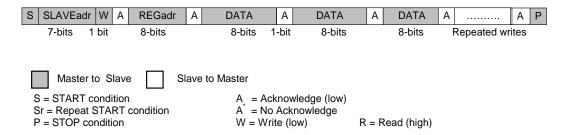


Figure 26: 2-WIRE Page Write (SDA Line)

Via control WRITE_MODE an alternate write mode can be configured. Register addresses and data are sent in alternation like in Figure 27 to support host repeated write operations that access several non-consecutive registers. Data will be stored at the previously received register address.



An update of WRITE_MODE cannot be done without interruption within a transmission frame. Thus, if not previously selected or not set as OTP default, the activation of Repeated Write must be done with a regular write on WRITE_MODE followed by a stop condition. The next frame after a start condition can be written in Repeated Write.

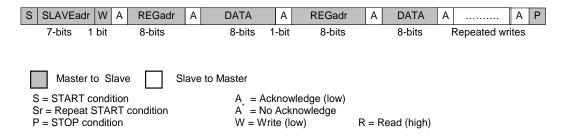


Figure 27: 2-WIRE Repeated Write (SDA Line)

If a new START or STOP condition occurs within a message, the bus will return to IDLE-mode.

7.5 Internal Temperature Supervision

To protect DA9223-A and DA9224-A from damage due to excessive power dissipation, the internal temperature is continuously monitored. There are three temperature thresholds:

Table 12: Over-Temperature Thresholds

Temperature Threshold	Typical Temperature Setting	Interrupt Event	Status Bit	Masking Bit
TEMP_WARN	125 °C	E_TEMP_WARN	TEMP_WARN	M_TEMP_WARN
TEMP_CRIT	140 °C	E_TEMP_CRIT	TEMP_CRIT	M_TEMP_CRIT
TEMP_POR	150 °C			

When the junction temperature reaches the TEMP_WARN threshold, DA9223-A and DA9224-A will assert the bit TEMP_WARN and will generate the event E_TEMP_WARN. If not masked using bit M_TEMP_WARN, the output port nIRQ will be asserted. The status bit TEMP_WARN will remain asserted as long as the junction temperature remains higher than TEMP_WARN.

When the junction temperature increases further to TEMP_CRIT, DA9223-A and DA9224-A will immediately disable the buck converter, assert the bit TEMP_CRIT, and will generate the event E_TEMP_CRIT. If not masked via bit M_TEMP_CRIT, the output port nIRQ will be asserted. The status bit TEMP_CRIT will remain asserted as long as the junction temperature remains higher than TEMP_CRIT. The buck converter will be kept disabled as long as the junction temperature is above TEMP_CRIT. It will not be automatically re-enabled even after the temperature drops below the valid threshold (even if the controlling GPI is asserted). A direct write into BUCKA_EN or BUCKB_EN, or a toggling of the controlling GPI, is needed to enable the buck converter.

Whenever the junction temperature exceeds TEMP_POR, a power on reset to the digital core is immediately asserted, which will stops all functionalities of DA9223-A and DA9224-A. This is needed to prevent possible permanent damage in the case of a rapid temperature increase.

DA9223-A and DA9224-A



Auto Grade 0.8 mm Pitch Multi-Phase Buck Converter

8 Register Definitions

8.1 Register Map

Table 13 displays the register map, where all bits loaded from OTP are marked in bold.



Table 13: Register Map

Addr	Function	7	6	5	4	3	2	1	0	
Auu	T direacii	,	,	Register I		,	2	'	•	
0x 00	PAGE CON	REVERT	WRITE MODE	Reserved	Reserved	Reserved		REG PAGE		
0.00	TAGE_GON	100 TOC 100 TO								
0x 50	STATUS A	Reserved	Reserved	Reserved	GPI4	GPI3	GPI2	GPI1	GPI0	
0x 51	STATUS_B	RAMP_READY_B	RAMP_READY_A	OV_CURR_B	OV_CURR_A	TEMP_CRIT	TEMP_WARN	PWRGOOD_B	PWRGOOD_A	
0x 52	EVENT_A	Reserved	E_UVLO_IO	Reserved	E_GPI4	E_GPI3	E_GPI2	E_GPI1	E_GPI0	
0x 53	EVENT_B	Reserved	Reserved	E_OV_CURR_B	E_OV_CURR_A	E_TEMP_CRIT	E_TEMP_WARN	E_PWRGOODB	E_PWRGOOD_A	
0x 54	MASK A	Reserved	M UVLO IO	Reserved	M GPI4	M GPI3	M GPI2	M GPI1	M GPI0	
0x 55	MASK_B	Reserved	Reserved	M_OV_CURR_B	M_OV_CURR_A	M_TEMP_CRIT	M_TEMP_WARN	M_PWRGOOD_B	M_PWRGOOD_A	
0x 56	CONTROL A	V LOCK	SLEW R			EW RATE A	W_IEWF_WARM	DEBOUNCING	III_FWRGOOD_A	
0x 58	GPI0-1	GPI1 MODE	GPI1_TYPE		PI1 PIN	GPI0 MODE	GPI0 TYPE		PIO PIN	
0x 59	GPIO2-3	GPIO3 MODE	GPIO3 TYPE		IO3 PIN	GPIO_MODE	GPIO2 TYPE		PIO2 PIN	
0x 5A	GPI4	Reserved	Reserved		eserved	GPI4 MODE	GPI4_TYPE		PI4 PIN	
0x5D	BUCKA_CONT	Reserved	VBUCK		VBUCKA_SEL	BUCKA_PD_DIS		CKA_GPI	BUCKA EN	
0x 5E	BUCKB_CONT	Reserved	VBUCK		VBUCKB_SEL	BUCKB_PD_DIS		CKB GPI	BUCKB EN	
UN UL	500.6_0011	110001100	1555.1	Register I		500115_1 5_510	50.		500.05_2.11	
0x 80	PAGE_CON	REVERT	WRITE MODE	Reserved	Reserved	Reserved		REG PAGE		
0.00	17102_0011	The Vactor	man E_mode	1000100	1000100	1000100		neo_rnot		
0x D0	BUCK_ILIM		BUCKB ILIM			I	BUC	KA ILIM		
0x D1	BUCKA_CONF		BUCKA DOWN CTRL						KA MODE	
0x D2	BUCKB_CONF		BUCKB DOWN CTRL			BUCKB_UP_CTRL BUCKB_MODE				
0x D3	BUCK_CONF	Reserved	Reserved	Reserved	PH_SH_EN_B	PH_SH_EN_A	PHASE_SEL_B			
0x D5	VBUCKA MAX	Reserved				VBUCKA MAX				
0x D6	VBUCKB_MAX	Reserved				VBUCKB MAX				
0x D7	VBUCKA_A	BUCKA_SL_A				VBUCKA A	VBUCKA_A			
0x D8	VBUCKA_B	BUCKA_SL_B				VBUCKA_B				
0x D9	VBUCKB_A	BUCKB_SL_A				VBUCKB_A				
0x DA	VBUCKB_B	BUCKB_SL_B				VBUCKB_B				
				Register I	Page 2					
0x 100	PAGE_CON	REVERT	WRITE_MODE	Reserved	Reserved	Reserved		REG_PAGE		
0x 105	INTERFACE		IF_BASE_ADDI	R1		R/W_POL	СРНА	CPOL	nCS_POL	
0x 106	INTERFACE2	IF_TYPE	PM_IF_HSM	PM_IF_FMP	PM_IF_V	Reserved	Reserved	Reserved	Reserved	
0x 143	CONFIG_A	Reserved	Reserved	Reserved	2WIRE_TO	GPI_V	Reserved	IRQ_TYPE	IRQ_LEVEL	
0x 144	CONFIG_B	UVLO_IO_DIS	PGB_DVC_MASK	PGA_DVC_MASK	0	CB_MASK	OC	A_MASK	RELOAD_FUNC_EN	
0x 145	CONFIG_C	Reserved	Reserved	Reserved	GPI4_PUPD	GPIO3_PUPD	GPIO2_PUPD	GPI1_PUPD	GPI0_PUPD	
0x 146	CONFIG_D	BUCKB_PG	SEL	BUCK	A_PG_SEL	READYB_	CONF	REA	DYA_CONF	
0x 147	CONFIG_E	STAND_ALONE	Reserved	Reserved	Reserved	Reserved		OSC_TUNE		
0x 148	CONFIG_F		IF_BASE_ADDI	12		Reserved	Reserved	ADDR	_SEL_CONF	
	Register Page 4									
0x 200	PAGE_CON	REVERT	WRITE_MODE	Reserved	Reserved	Reserved		REG_PAGE		
0x 201	DEVICE_ID				DE\	/_ID				
0x 202	VARIANT_ID		MRC					VRC		
0x 203	CUSTOMER_ID				cus	t_id				
0x 204	CONFIG_ID				CONFI	IG_REV				



8.2 Register Definitions

8.2.1 Register Page Control

Register	Bit	Туре	Label	Description
	7	R/W	REVERT	Resets REG_PAGE to 000 after read/write access has finished
	6	R/W	WRITE_MODE	2-WIRE multiple write mode (Note 1) 0: Page Write Mode 1: Repeated Write Mode
	5:3	R/W	(reserved)	
0x00 PAGE_CON	2:0	R/W	REG_PAGE	I ² C 00x: Selects Register 0x00 to 0xFF 01x: Selects Register 0x100 to 0x17F 10x: Selects Register 0x200 to 0x27F SPI 000: Selects Register 0x00 to 0x7F 001: Selects Register 0x80 to 0xFF 010: Selects Register 0x100 to 0x17F 100: Selects Register 0x200 to 0x27F

Note 1 Not used for 4-WIRE-IF.

8.2.2 Register Page 0

8.2.2.1 System Control and Event

The STATUS registers report the current value of the various signals at the time that it is read out.

Register	Bit	Туре	Label	Description
	7:5	R	(reserved)	
	4	R	GPI4	GPI4 level
0x50	3	R	GPI3	GPI3 level
STATUS_A	2	R	GPI2	GPI2 level
	1	R	GPI1	GPI1 level
	0	R	GPI0	GPI0 level

Register	Bit	Туре	Label	Description
	7	R	RAMP_READY_B	De-asserted during Buck A DVC, power up and power down
			RAMP_READY_A	De-asserted during Buck B DVC, power up and power down
0x51	5	R	OV_CURR_B	Asserted as long as the current limit for Buck B is hit
STATUS_B	4	R	OV_CURR_A	Asserted as long as the current limit for Buck A is hit
	3	R	TEMP_CRIT	Asserted as long as the thermal shutdown threshold is reached
	2	R	TEMP_WARN	Asserted as long as the thermal warning threshold is reached



Register	Bit	Туре	Label	Description
	1	R	PWRGOOD_B	Asserted as long as the Buck B output voltage is in range
	0	R	PWRGOOD_A	Asserted as long as the Buck A output voltage is in range

The EVENT registers hold information about events that have occurred in DA9223-A and DA9224-A. Events are triggered by a change in the status register which contains the status of monitored signals. When an EVENT bit is set in the event register, the IRQ signal is asserted unless the event is masked by a bit in the mask register. **The IRQ triggering event register will be cleared from the host by writing back its read value.** New events occurring during clearing will be delayed before they are passed to the event register, ensuring that the host controller does not miss them.

Register	Bit	Туре	Label	Description
	7	R	(reserved)	
	6	R	E_UVLO_IO	UVLO_IO caused event
	5	R	(reserved)	
0x52	4	R	E_GPI4	GPI4 event according to active state setting
EVENT_A	3	R	E_GPI3	GPI3 event according to active state setting
	2	R	E_GPI2	GPI2 event according to active state setting
	1	R	E_GPI1	GPI1 event according to active state setting
	0	R	E_GPI0	GPI0 event according to active state setting

Register	Bit	Туре	Label	Description
	7:6	R	(reserved)	
	5	R	E_OV_CURR_B	OV_CURR Buck B caused event
	4	R	E_OV_CURR_A	OV_CURR Buck A caused event
0x53 EVENT B	3	R	E_TEMP_CRIT	TEMP_CRIT caused event
LVLINI_B	2	R	E_TEMP_WARN	TEMP_WARN caused event
	1	R	E_PWRGOOD_B	PWRGOOD loss at Buck B caused event
	0	R	E_PWRGOOD_A	PWRGOOD loss at Buck A caused event

Register	Bit	Туре	Label	Description
	7	R/W	(reserved)	
	6	R/W	M_UVLO_IO	Mask UVLO_IO caused nIRQ
	5	R/W	(reserved)	
0x54	4	R/W	M_GPI4	Mask nIRQ interrupt at GPI4
MASK_A	3	R/W	M_GPI3	Mask nIRQ interrupt at GPI3
	2	R/W	M_GPI2	Mask nIRQ interrupt at GPI2
	1	R/W	M_GPI1	Mask nIRQ interrupt at GPI1
	0	R/W	M_GPI0	Mask nIRQ interrupt at GPI0



Register	Bit	Туре	Label	Description
	7:6	R/W	(reserved)	
	5	R/W	M_OV_CURR_B	Mask OV_CURR Buck B caused nIRQ and event
	4	R/W	M_OV_CURR_A	Mask OV_CURR Buck A caused nIRQ and event
0x55 MASK B	3	R/W	M_TEMP_CRIT	Mask TEMP_CRIT caused nIRQ
WIX CON_D	2	R/W	M_TEMP_WARN	Mask TEMP_WARN caused nIRQ
	1	R/W	M_PWRGOOD_B	Mask PWRGOOD Buck B caused nIRQ
	0	R/W	M_PWRGOOD_A	Mask PWRGOOD Buck A caused nIRQ

Register	Bit	Туре	Label	Description
	7	R/W	V_LOCK	0: Allows host writes into registers 0xD0 to 0x14F 1: Disables register 0xD0 to 0x14F reprogramming from control interfaces
	6:5	R/W	SLEW_RATE_B	Buck B DVC slewing is executed at 00: 10mV every 4.0 µs 01: 10mV every 2.0 µs 10: 10mV every 1.0 µs 11: 10mV every 0.5 µs
0x56 CONTROL_A	4:3	R/W	SLEW_RATE_A	Buck A DVC slewing is executed at 00: 10mV every 4.0 µs 01: 10mV every 2.0 µs 10: 10mV every 1.0 µs 11: 10mV every 0.5 µs
	0:2	R/W	DEBOUNCE	Input signals debounce time: 000: no debounce time 001: 0.1 ms 010: 1.0 ms 011: 10 ms 100: 50 ms 101: 250 ms 110: 500 ms 111: 1000 ms

8.2.2.2 **GPIO** Control

Register	Bit	Туре	Label	Description
0x58 GPI0-1	7	R/W	GPI1_MODE	0: GPI: debouncing off 1: GPI: debouncing on
	6	R/W	GPI1_TYPE	0: GPI: active low 1: GPI: active high
	5:4	R/W	GPI1_PIN	PIN assigned to: 00: GPI >00: Reserved
	3	R/W	GPI0_MODE	0: GPI: debouncing off 1: GPI: debouncing on



Register	Bit	Туре	Label	Description
	2	R/W	GPI0_TYPE	0: GPI: active low 1: GPI: active high
	1:0	R/W	GPI0_PIN	PIN assigned to: 00: GPI 01: Track enable 1x: Reserved

Register	Bit	Туре	Label	Description
	7	R/W	GPIO3_MODE	O: GPI: debouncing off GPO: Sets output to passive level 1: GPI: debouncing on GPO: Sets output to active level
	6	R/W	GPIO3_TYPE	0: GPI/GPO: active low 1: GPI/GPO: active high
0x59	5:4	R/W	GPIO3_PIN	PIN assigned to: 00: GPI 01: Reserved 10: GPO (Open drain) 11: GPO (Push-pull)
GPIO2-3	3	R/W	GPIO2_MODE	O: GPI: debouncing off GPO: Sets output to passive level 1: GPI: debouncing on GPO: Sets output to active level
2	2	R/W	GPIO2_TYPE	0: GPI/GPO: active low 1: GPI/GPO: active high
	1:0	R/W	GPIO2_PIN	PIN assigned to: 00: GPI 01: Reserved 10: GPO (Open drain) 11: GPO (Push-pull)

Register	Bit	Туре	Label	Description
	7:4	R/W	(reserved)	
_	3	R/W	GPI4_MODE	0: GPI: debouncing off 1: GPI: debouncing on
	2	R/W	GPI4_TYPE	0: GPI: active low 1: GPI: active high
	1:0	R/W	GPI4_PIN	PIN assigned to: 00: GPI 01: Reserved 1x: Reserved

© 2022 Renesas Electronics



8.2.2.3 Regulators Control

Register	Bit	Туре	Label	Description
	7	R/W	(reserved)	
				Selects the GPI that specifies the target voltage of VBUCKA. This is VBUCKA_A on active to passive transition, VBUCKA_B on passive to active transition. Active high/low is controlled by GPIx_TYPE.
	6:5	R/W	VBUCKA_GPI	00: Not controlled by GPIO
				01: GPI1 controlled
				10: GPIO2 controlled
				11: GPI4 controlled
			VBUCKA_SEL	Buck A voltage is selected from (ramping):
0x5D	4	R/W		0: VBUCKA_A
BUCKA_CON				1: VBUCKA_B
Т		5 444	R/W BUCKA_PD_DIS	0: Enable pull-down resistor of Buck A when the buck is disabled
	3	R/VV		Disable pull-down resistor of Buck A when the buck is disabled
				GPI enables the Buck A on passive to active state transition, disables the Buck A on active to passive state transition
	2:1	R/W	BUCKA_GPI	00: Not controlled by GPIO
				01: GPI0 controlled
				10: GPI1 controlled
				11: GPIO3 controlled
	0	R/W	BUCKA_EN	0: Buck A disabled
	-		· <u>=</u>	1: Buck A enabled

Register	Bit	Туре	Label	Description
	7	R/W	(reserved)	
				Selects the GPI that specifies the target voltage of VBUCKB. This is VBUCKB_A on active to passive transition, VBUCKB_B on passive to active transition.
	6:5	R/W	VBUCKB_GPI	Active high/low is controlled by GPIx_TYPE
				00: Not controlled by GPIO
0x5E				01: GPI1 controlled
BUCKB CON				10: GPIO2 controlled
Т _				11: GPI4 controlled
	4	R/W	VBUCKB_SEL	Buck A voltage is selected from (ramping): 0: VBUCKB_A 1: VBUCKB_B
	3	3 R/W	BUCKB PD DIS	0: Enable pull-down resistor of Buck B when the buck is disabled
	3	11/1	BOOKD_FD_DIG	Disable pull-down resistor of Buck B when the buck is disabled

© 2022 Renesas Electronics



Register	Bit	Туре	Label	Description
		R/W	BUCKB GPI	GPI enables the Buck B on passive to active state transition, disables the Buck B on active to passive state transition
	2:1 F			00: Not controlled by GPIO
				01: GPI0 controlled
				10: GPI1 controlled
				11: GPIO3 controlled
	0	R/W	BUCKB_EN	0: Buck B disabled 1: Buck B enabled

8.2.3 Register Page 1

Register	Bit	Туре	Label	Description
	7	R/W	REVERT	Resets REG_PAGE to 000 after read/write access has finished
	6	R/W	WRITE_MODE	2-WIRE multiple write mode 0: Page Write Mode 1: Repeated Write Mode
	5:3	R/W	(reserved)	
0x80 PAGE_CON	2:0	R/W	REG_PAGE	I ² C 00x: Selects Register 0x00 to 0xFF 01x: Selects Register 0x100 to 0x17F 10x: Selects Register 0x200 to 0x27F SPI 000: Selects Register 0x00 to 0x7F 001: Selects Register 0x80 to 0xFF 010: Selects Register 0x100 to 0x17F 100: Selects Register 0x200 to 0x27F

8.2.3.1 Regulators Settings

Register	Bit	Туре	Label	Description
0xD0 BUCK_ILIM	7:4	R/W	BUCKB_ILIM	Current limit per phase: 0000: 4000 mA 0001: 4200 mA 0010: 4400 mA continuing through 1001: 5800 mA to 1110: 6800 mA 1111: 7000 mA



Register	Bit	Туре	Label	Description
Register	3:0	R/W	BUCKA_ILIM	Current limit per phase: 0000: 4000 mA 0001: 4200 mA 0010: 4400 mA continuing through 1001: 5800 mA to 1110: 6800 mA 1111: 7000 mA

Register	Bit	Туре	Label	Description
	7:5	R/W	BUCKA_DOWN_ CTRL	Buck A voltage ramping during power down 000: 1.25 mV/µs 001: 2.5 mV/µs 010: 5 mV/µs 011: 10 mV/µs 100: 20 mV/µs 101: 30 mV/µs 111: Reserved
0xD1 BUCKA_CON F	4:2	R/W	BUCKA_UP_CT RL	Buck A voltage ramping during start up 000: 1.25 mV/µs 001: 2.5 mV/µs 010: 5 mV/µs 011: 10 mV/µs 100: 20 mV/µs (Note 1) 101: 30 mV/µs 110: 40 mV/µs 111: target voltage applied immediately (no soft start)
	1:0	R/W	BUCKA_MODE	00: PFM/PWM mode controlled via voltage A and B registers 01: Automatic mode (1-phase) 10: Buck A always operates in PWM mode 11: Automatic mode

Note 1 Settings higher than 20 mV/ μ s may cause significant overshoot.



Register	Bit	Туре	Label	Description
				Buck B voltage ramping during power down
				000: 1.25 mV/μs
				001: 2.5 mV/μs
			DUCKE DOWN	010: 5 mV/μs
	7:5	R/W	BUCKB_DOWN_ CTRL	011: 10 mV/µs
			• · · · · =	100: 20 mV/µs
				101: 30 mV/µs
				110: 40 mV/µs
				111: Reserved
			BUCKB_UP_CT RL	Buck B voltage ramping during start up
0xD2				000: 1.25 mV/μs
BUCKB_CON				001: 2.5 mV/μs
F				010: 5 mV/μs
	4:2	R/W		011: 10 mV/µs
				100: 20 mV/µs (Note 1)
				101: 30 mV/µs
				110: 40 mV/µs
				111: target voltage applied immediately (no soft start)
				00: PFM/PWM mode controlled via voltage A and B registers
	1:0	R/W	BUCKB_MODE	01: Automatic mode (1-phase)
			_	10: Buck B always operates in PWM mode
				11: Automatic mode

Note 1 Settings higher than 20mV/µs may cause significant overshoot.

Register	Bit	Туре	Label	Description
	7:5	R/W	(reserved)	
	4	R/W	PH_SH_EN_B	Enable current dependent phase shedding in PWM for Buck B
	3	R/W	PH_SH_EN_A	Enable current dependent phase shedding in PWM for Buck A
		R/W	PHASE_SEL_B	Phase selection for Buck B in PWM
0xD3	2			0: 1 phase is selected
BUCK CONF				1: 2 phases are selected
BOCK_CONF		R/W		Phase selection for Buck A in PWM mode. Settings >01 apply only for DA9223-A otherwise the number of phases is limited to max 2
	1.0		DHACE CEL A	00: 1 phase is selected
	1:0		PHASE_SEL_A	01: 2 phases are selected
				10: 3 phases are selected (uneven 0/90/180 phase shift)
				11: 4 phases are selected



Register	Bit	Туре	Label	Description
	7	R/W	(reserved)	
				Sets the maximum voltage allowed for Buck A (OTP programmed, access only in test mode)
				0000000: 0.30 V
				0000001: 0.31 V
0xD5				0000010: 0.32 V
VBUCKA_MA X	6:0	R	VBUCKA_MAX	Continuing through
				1000110: 1.0 V
				to
				1111101: 1.55 V
				111110: 1.55 V
				1111111: 1.57 V

Register	Bit	Туре	Label	Description
	7	R/W	(reserved)	
				Sets the maximum voltage allowed for Buck B (OTP programmed, access only in test mode)
				0000000: 0.30 V
				0000001: 0.31 V
0xD6				0000010: 0.32 V
VBUCKB_MA X	6:0	R	VBUCKB_MAX	Continuing through
				1000110: 1.0 V
				to
				1111101: 1.55 V
				1111110: 1.56 V
				1111111: 1.57 V



Register	Bit	Туре	Label	Description
	7	R/W	BUCKA_SL_A	0: Configures Buck A to PWM mode whenever selecting A voltage setting
		TX/ VV		Configures Buck A to automatic mode whenever selecting A voltage setting
				0000000: 0.30 V
		R/W	VBUCKA_A	0000001: 0.31 V
0xD7				0000010: 0.32 V
VBUCKA_A				Continuing through
	6:0			1000110: 1.0 V
				to
				1111101: 1.55 V
				1111110: 1.56 V
				1111111: 1.57 V

Register	Bit	Туре	Label	Description
	7	R/W	BUCKA_SL_B	O: Configures Buck A to PWM mode, whenever selecting B voltage setting 1: Configures Buck A to automatic mode, whenever selecting B voltage setting
0xD8 VBUCKA_B	6:0	R/W	VBUCKA_B	0000000: 0.30 V 0000001: 0.31 V 0000010: 0.32 V Continuing through 1000110: 1.0 V to 1111101: 1.55 V 1111111: 1.56 V 1111111: 1.57 V
Register	Bit	Туре	Label	Description
	7	R/W	BUCKB_SL_A	O: Configures Buck B to PWM mode, whenever selecting A voltage setting 1: Configures Buck B to automatic mode, whenever selecting A voltage setting
0xD9 VBUCKB_A	6:0	R/W	VBUCKB_A	0000000: 0.30 V 0000001: 0.31 V 0000010: 0.32 V Continuing through 1000110: 1.0 V to 1111101: 1.55 V 1111111: 1.56 V 1111111: 1.57 V



Register	Bit	Туре	Label	Description
	7	R/W	BUCKB_SL_B	O: Configures Buck B to PWM mode, whenever selecting B voltage setting 1: Configures Buck B to automatic mode, whenever selecting B voltage setting
0xDA VBUCKB_B	6:0	R/W	VBUCKB_B	0000000: 0.30 V 0000001: 0.31 V 0000010: 0.32 V Continuing through 1000110: 1.0 V to 1111101: 1.55 V 1111111: 1.56 V 1111111: 1.57 V

8.2.4 Register Page 2

Register	Bit	Туре	Label	Description
	7	R/W	REVERT	Resets REG_PAGE to 000 after read/write access has finished
	6	R/W	WRITE_MODE	2-WIRE multiple write mode 0: Page Write Mode 1: Repeated Write Mode
	5:3	R/W	(reserved)	
0x100 PAGE_CON	2:0	R/W	REG_PAGE	I ² C 00x: Selects Register 0x00 to 0xFF 01x: Selects Register 0x100 to 0x17F 10x: Selects Register 0x200 to 0x27F SPI 000: Selects Register 0x00 to 0x7F 001: Selects Register 0x80 to 0xFF 010: Selects Register 0x100 to 0x17F 100: Selects Register 0x200 to 0x27F



8.2.4.1 Interface and OTP Settings (Shared with DA9063)

Register	Bit	Туре	Label	Description
				4 MSB of 2-WIRE control interfaces base address XXXX0000
				11010000 = 0xD0 write address of PM 2-WIRE interface (page 0 and 1)
				11010001 = 0xD1 read address of PM 2-WIRE interface (page 0 and 1)
	7:4	R/W	IF_BASE_ADDR	11010010 = 0xD2 write address of PM-2-WIRE interface (page 2 and 3)
			1	11010011 = 0xD3 read address of PM-2-WIRE interface (page 2 and 3)
0x105 INTERFACE				11010101 = 0xD5 read address of PM-2-WIRE interface (page 4 and 5)
				Code '0000' is reserved for unprogrammed OTP (triggers start-up with hardware default interface address)
				4-WIRE: Read/Write bit polarity
	3	R/W	R/W_POL	0: Host indicates reading access via R/W bit = '0'
				1: Host indicates reading access via R/W bit = '1'
	2	R/W	СРНА	4-WIRE interface clock phase (see Table 10)
				4-WIRE interface clock polarity
	1	R/W	CPOL	0: SK is low during idle
				1: SK is high during idle
				4-WIRE chip select polarity
	0	R/W	nCS_POL	0: nCS is low active
				1: nCS is high active



Register	Bit	Туре	Label	Description
0x106 INTERFACE2	7	R/W	IF_TYPE	O: Power manager interface is 4-WIRE. Automatically configures GPIO3 and GPI4 as interface signals. The GPIO configuration is overruled. 1: Power manager interface is 2-WIRE
	6	R/W	PM_IF_HSM	Enables continuous high speed mode on 2-WIRE interface if asserted (no master code required)
	5	R/W	PM_IF_FMP	Enables 2-WIRE interface operating with fast mode+ timings if asserted
	4	R/W	PM_IF_V	O: Power manager interface in 2-WIRE mode is supplied from VDDCORE (4-WIRE always from VDDIO) 1: Power manager interface in 2-WIRE mode is
				supplied from VDDIO (4-WIRE always from VDDIO)
	0:3	R/W	(reserved)	

8.2.4.2 Application Configuration Settings

Register	Bit	Туре	Label	Description
0x143	7:5	R/W	(reserved)	
	4	R/W	2WIRE_TO	Enables automatic reset of 2-WIRE interface if the clock stays low for >35 ms 0: Disabled 1: Enabled
	3	R/W	GPI_V	GPIs are supplied from: 0: VDDCORE 1: VDDIO
CONFIG_A	2	R/W	(reserved)	
	1	R/W	IRQ_TYPE	nIRQ output port is: 0: Push-pull 1: Open drain (requires external pull-up resistor)
	0	R/W	IRQ_LEVEL	nIRQ output port is: 0: Active low 1: Active high

Register	Bit	Туре	Label	Description
0x144 CONFIG_B	7	R/W	UVLO_IO_DIS	Disable the UVLO for the VDDIO rail and its comparator (suggested for rail voltages different to 1.8 V and to save quiescent current)
	6	R/W	PGB_DVC_MAS K	Power-good configuration for Buck B 0: Power-good signal not masked during DVC transitions 1: Power-good signal masked during DVC transitions (keep previous status)
	5	R/W	PGA_DVC_MAS K	Power-good configuration for Buck A 0: Power-good signal not masked during DVC transitions 1: Power-good signal masked during DVC transitions (keep previous status)



Register	Bit	Туре	Label	Description
				Over Current configuration for Buck B
				00: Event generation due to over current hit is always active during DVC transitions of the Buck converter
	4:3	R/W	OCB MASK	01: Event generation due to over current hit is masked during DVC transitions of the buck converter + 2 μs extra masking at the end
	4.3	10,00	COD_IVI/IOI	10: Event generation due to over current hit is masked during DVC transitions of the buck converter + 10 μs extra masking at the end
				11: Event generation due to over current hit is masked during DVC transitions of the buck converter + 50 μs extra masking at the end
		I R/W	OCA_MASK	Over Current configuration for Buck A
	2:1			00: Event generation due to over current hit is always active during DVC transitions of the buck converter
				01: Event generation due to over current hit is masked during DVC transitions of the buck converter + 2 μs extra masking at the end
	2.1			10: Event generation due to over current hit is masked during DVC transitions of the buck converter + 10 μs extra masking at the end
				11: Event generation due to over current hit is masked during DVC transitions of the buck converter + 50 μs extra masking at the end
	0	R/W	RELOAD_FUNC _EN	Enable the OTP re-load function for GPI0 when configured as input port

Register	Bit	Туре	Label	Description
	7:5	R/W	(reserved)	
	4	R/W	GPI4_PUPD	GPI: pull-down resistor disabled GPI: pull-down resistor enabled
0x145 CONFIG_C	3	R/W	GPIO3_PUPD	0: GPI: pull-down resistor disabled GPO (open drain): pull up resistor disabled (external pull-up resistor) 1: GPI: pull-down resistor enabled GPO (open drain): pull up resistor
	2	R/W	GPIO2_PUPD	O: GPI: pull-down resistor disabled GPO (open drain): pull up resistor disabled (external pull-up resistor) 1: GPI: pull-down resistor enabled GPO (open drain): pull up resistor enabled
	1	R/W	GPI1_PUPD	GPI: pull-down resistor disabled GPI: pull-down resistor enabled
	0	R/W	GPI0_PUPD	0: GPI: pull-down resistor disabled 1: GPI: pull-down resistor enabled



Register	Bit	Туре	Label	Description
	7:6 R/W 5:4 R/W		BUCKB_PG_SEL BUCKA_PG_SEL	Selection of the PG signal for Buck B 00: none 01: GPO2 10: GPO3 11: reserved Selection of the PG signal for Buck A 00: none 01: GPO2
				10: GPO3 11: reserved
CONFIG_D	3:2	R/W	READYB_CONF	Selection of the READY signal for Buck B 00: none 01: GPO2 10: GPO3 11: reserved
	1:0 R/W READYA_	READYA_CONF	Selection of the READY signal for Buck A 00: none 01: GPO2 10: GPO3 11: reserved	

Register	Bit	Туре	Label	Description
	7	R/W	STAND_ALONE	0: DA9223-A and DA9224-A is used as companion IC to DA9063 or DA9063-compliant 1: DA9223-A and DA9224-A is stand alone or as companion IC with another PMU not DA9063-compliant
	6:5	R/W	(reserved)	
	4:3	R/W	(reserved)	
0x147 CONFIG_E	2:0	R/W	OSC_TUNE	Tune the main 6 MHz oscillator frequency: 000: no tune 001: +180 kHz 010: +360 kHz 011: +540 kHz 100: +720 kHz 101: +900 kHz 110: +1080 kHz 111: +1260 kHz



Register	Bit	Туре	Label	Description
				If a second I ² C address is to be selected on ADR_SEL_CONF, this field configures the second address.
				4 MSB of 2-WIRE control interfaces base address XXXX0000
				11010000 = 0xD0 write address of PM 2-WIRE interface (page 0 and 1)
	7:4	R/W	IF_BASE_ADDR 2	11010001 = 0xD1 read address of PM 2-WIRE interface (page 0 and 1)
7:4	7:4	R/VV		11010010 = 0xD2 write address of PM-2-WIRE interface (page 2 and 3)
0x148				11010011 = 0xD3 read address of PM-2-WIRE interface (page 2 and 3)
CONFIG_F				11010101 = 0xD5 read address of PM-2-WIRE interface (page 4 and 5)
				Code '0000' is reserved for unprogrammed OTP (triggers start-up with hardware default interface address)
	3:2	R	(reserved)	
				Selects the GPI for the alternative I ² C address selection:
		DAM	ADDR SEL CO	00: none
	1	R/W	NF	01: GPI0
				10: GPI1
				11: GPI4



8.2.5 Register Page 4

Register	Bit	Туре	Label	Description
	7	7 R/W REVERT		Resets REG_PAGE to 000 after read/write access has finished
	6	R/W	WRITE_MODE	2-WIRE multiple write mode 0: Page Write Mode 1: Repeated Write Mode
	5:3	R/W	(reserved)	
0x200 PAGE_CON	2:0	R/W	REG_PAGE	I ² C 00x: Selects Register 0x00 to 0xFF 01x: Selects Register 0x100 to 0x17F 10x: Selects Register 0x200 to 0x27F SPI 000: Selects Register 0x00 to 0x7F 001: Selects Register 0x80 to 0xFF 010: Selects Register 0x100 to 0x17F 100: Selects Register 0x200 to 0x27F

8.2.5.1 Chip and OTP IDs

Register	Bit	Туре	Label	Description
0x201 DEVICE_ID	7:0	R	DEV_ID	Device ID

Register	Bit	Туре	Label	Description	
0x202	7:4	R	MRC	Mask Revision Code	
VARIANT_ID	3:0	R	VRC	Chip Variant Code	

Register	Bit	Туре	Label	Description
0x203 CUSTOMER_ ID	7:0	R	CUST_ID	Customer ID

Register	Bit	Туре	Label	Description
0x204 CONFIG_ID	7:0	R	CONFIG_REV	OTP Variant



9 Application Information

The following recommended components are examples selected from requirements of a typical application.

9.1 Capacitor Selection

Ceramic capacitors are used as bypass capacitors at all VDD and output rails. When selecting a capacitor, especially for types with high capacitance at smallest physical dimension, the DC bias characteristic has to be taken into account.

Table 14: Recommended Capacitor Types

Application	Value	Size	Temp Char	Tol	V-Rate	Туре
VOUT output bypass	47 uF	1210	X7R ±15 %	±10 %	6.3 V	Murata GCM32ER70J476KE19
	22 uF	1206	X7R ±15 %	±10 %	6.3 V	Murata GCM31CR70J226KE23
	10 uF	0805	X7R ±15 %	±10 %	6.3 V	Murata GCM21BR70J106KE22
VDDx bypass	10 uF	0805	X7R ±15 %	±10 %	10 V	Murata GCM21BR71A106KE22
VSYS bypass	1 uF	0603	X7R ±15 %	±10 %	16 V	Murata GCM188R71C105KA64
VDDIO bypass	100 nF	0402	X7R ±15 %	±10 %	50 V	Murata GCM155R71H104KE02



9.2 Inductor Selection

Inductors should be selected based upon the following parameters:

- Rated max. current: usually a coil provides two current limits: The Isat specifies the maximum current at which the inductance drops by 30 % of the nominal value. The Imax is defined by the maximum power dissipation and is applied to the effective current.
- DC resistance: critical for the converter efficiency and should therefore be minimized.
- The typical recommended output inductance is 0.22 µH per phase. Use of larger output inductance degrades the load transient performance of the buck converter.

Table 15: Recommended Inductor Types

Application	Value	Size	lmax(dc)	Isat	Tol	DC res	Туре
BUCK	0.22 uH	2.5 mm x 2.0 mm x 1.0 mm	7.1 A	8.0 A	±20%	12 mΩ	TDK TFM252010ALMAR22M TAA
	0.22 uH	2.5 mm x 2.0 mm x 1.2 mm	8.5 A	10 A	±20%	8 mΩ	TDK TFM252012ALMAR22M TAA
	0.24 uH	2.0 mm x 1.6 mm x 1.0 mm	7.0 A	7.5 A	±20%	15 mΩ	TDK TFM201610ALMAR24M TAA
	0.24 uH	2.0 mm x 1.6 mm x 1.2 mm	4.8 A	5.9 A	±20%	16 mΩ	TOKO DFE201612PD- R24M
	0.47 uH	2.5 mm x 2.0 mm x 1.0 mm	5.4 A	6.5 A	±20%	20 mΩ	TDK TFM252010ALMAR47M TAA
	0.47 uH	2.5 mm x 2.0 mm x 1.2 mm	5.6 A	6.5 A	±20%	19 mΩ	TDK TFM252012ALMAR47M TAA
	0.47 uH	2.5 mm x 2.0 mm x 1.2 mm	4.7 A	6.1 A	±20%	21 mΩ	TOKO DFE252012PD- R47M
	0.47 uH	2.0 mm x 1.6 mm x 1.0 mm	5.0 A	5.8 A	±20%	28 mΩ	TDK TFM201610ALMAR47M TAA
	0.47 uH	2.0 mm x 1.6 mm x 1.2 mm	3.8 A	4.5 A	±20%	26 mΩ	TOKO DFE201612PD- R47M
	0.24 uH	2.0 mm x 1.6 mm x 1.2 mm	5.0 A	7.7 A	±20%	16 mΩ	Taiyo Yuden MEMK2016TR24MV
	0.47 uH	2.0 mm x 1.6 mm x 1.2 mm	3.8 A	5.5 A	±20%	28 mΩ	Taiyo Yuden MEMK2016TR47MV
	0.24 uH	2.5 mm x 2.0 mm x 1.2 mm	5.9 A	8.5 A	±20%	13 mΩ	Taiyo Yuden MEMK2520TR24MV
	0.47 uH	2.5 mm x 2.0 mm x 1.2 mm	4.7 A	6.2 A	±20%	21 mΩ	Taiyo Yuden MEMK2520TR47MV



10 Package Information

10.1 Package Outlines

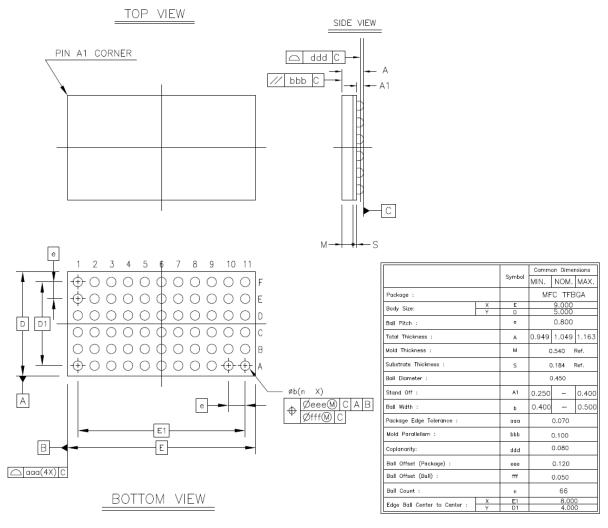
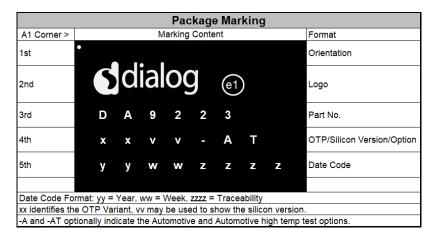


Figure 28: DA9223-A/24-A 66 TFBGA 0.8 mm Pitch Package Outline Drawing



10.2 Package Marking

Table 16: Package Marking



11 Ordering Information

The ordering number consists of the part number followed by a suffix indicating the packing method. For details and availability, please consult Dialog Semiconductor's website or your local sales representative.

Table 17: Ordering Information

Part Number	Package	Package Description	Comment	Package Outline
DA9223-xxFT1BB-A	66 TFBGA	Tray	Auto Grade 2	
DA9223-xxFT2BB-A, Note 1	66 TFBGA	T&R, 3000pcs	Auto Grade 2	
DA9223-xxFTDBB-A	66 TFBGA	T&R, 2200pcs	Auto Grade 2	
DA9224-xxFT1BB-A	66 TFBGA	Tray	Auto Grade 2	
DA9224-xxFT2BB-A, Note 1	66 TFBGA	T&R, 3000pcs	Auto Grade 2	
DA9224-xxFTDBB-A	66 TFBGA	T&R, 2200pcs	Auto Grade 2	
DA9223-xxFT1BB-AT	66 TFBGA	Tray	Auto Grade 2 with High Temp screening	
DA9223-xxFT2BB-AT, Note 1	66 TFBGA	T&R, 3000pcs	Auto Grade 2 with High Temp screening	Figure 28
DA9223-xxFTDBB-AT	66 TFBGA	T&R, 2200pcs	Auto Grade 2 with High Temp screening	
DA9224-xxFT1BB-AT	66 TFBGA	Tray	Auto Grade 2 with High Temp screening	
DA9224-xxFT2BB-AT, Note 1	66 TFBGA	T&R, 3000pcs	Auto Grade 2 with High Temp screening	
DA9224-xxFTDBB-AT	66 TFBGA	T&R, 2200pcs	Auto Grade 2 with High Temp screening	

Note 1 Large reel sizes are no longer supported, contact sales for further information

DA9223-A and DA9224-A



Auto Grade 0.8 mm Pitch Multi-Phase Buck Converter

Status Definitions

Revision	Datasheet Status	Product Status	Definition
1. <n></n>	Target	Development	This datasheet contains the design specifications for product development. Specifications may be changed in any manner without notice.
2. <n></n>	Preliminary	Qualification	This datasheet contains the specifications and preliminary characterization data for products in pre-production. Specifications may be changed at any time without notice in order to improve the design.
3. <n></n>	Final	Production	This datasheet contains the final specifications for products in volume production. The specifications may be changed at any time in order to improve the design, manufacturing and supply. Major specification changes are communicated via Customer Product Notifications. Datasheet changes are communicated via www.dialog-semiconductor.com.
4. <n></n>	Obsolete	Archived	This datasheet contains the specifications for discontinued products. The information is provided for reference only.

^{© 2022} Dialog Semiconductor. All rights reserved.

RoHS Compliance

Dialog Semiconductor's suppliers certify that its products are in compliance with the requirements of Directive 2011/65/EU of the European Parliament on the restriction of the use of certain hazardous substances in electrical and electronic equipment. RoHS certificates from our suppliers are available on request.

Notice

- 1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. Renesas Electronics disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, or information.
- Renesas Electronics hereby expressly disclaims any warranties against and liability for infringement or any other claims involving patents, copyrights, or other intellectual property rights of third parties, by or arising from the use of Renesas Electronics products or technical information described in this document, including but not limited to, the product data, drawings, charts, programs, algorithms, and application examples.
- No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
- 4. You shall be responsible for determining what licenses are required from any third parties, and obtaining such licenses for the lawful import, export, manufacture, sales, utilization, distribution or other disposal of any products incorporating Renesas Electronics products, if required.
- 5. You shall not alter, modify, copy, or reverse engineer any Renesas Electronics product, whether in whole or in part. Renesas Electronics disclaims any and all liability for any losses or damages incurred by you or third parties arising from such alteration, modification, copying or reverse engineering.
- 6. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The intended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.
 - "Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; industrial robots; etc.
 - "High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control (traffic lights); large-scale communication equipment; key financial terminal systems; safety control equipment; etc.

Unless expressly designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not intended or authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems; surgical implantations; etc.), or may cause serious property damage (space system; undersea repeaters; nuclear power control systems; aircraft control systems; key plant systems; military equipment; etc.). Renesas Electronics disclaims any and all liability for any damages or losses incurred by you or any third parties arising from the use of any Renesas Electronics product that is inconsistent with any Renesas Electronics data sheet, user's manual or other Renesas Electronics document.

- 7. No semiconductor product is absolutely secure. Notwithstanding any security measures or features that may be implemented in Renesas Electronics hardware or software products, Renesas Electronics shall have absolutely no liability arising out of any vulnerability or security breach, including but not limited to any unauthorized access to or use of a Renesas Electronics product or a system that uses a Renesas Electronics product. RENESAS ELECTRONICS DOES NOT WARRANT OR GUARANTEE THAT RENESAS ELECTRONICS PRODUCTS, OR ANY SYSTEMS CREATED USING RENESAS ELECTRONICS PRODUCTS WILL BE INVULNERABLE OR FREE FROM CORRUPTION, ATTACK, VIRUSES, INTERFERENCE, HACKING, DATA LOSS OR THEFT, OR OTHER SECURITY INTRUSION ("Vulnerability Issues"). RENESAS ELECTRONICS DISCLAIMS ANY AND ALL RESPONSIBILITY OR LIABILITY ARISING FROM OR RELATED TO ANY VULNERABILITY ISSUES. FURTHERMORE, TO THE EXTENT PERMITTED BY APPLICABLE LAW, RENESAS ELECTRONICS DISCLAIMS ANY AND ALL WARRANTIES, EXPRESS OR IMPLIED, WITH RESPECT TO THIS DOCUMENT AND ANY RELATED OR ACCOMPANYING SOFTWARE OR HARDWARE, INCLUDING BUT NOT LIMITED TO THE IMPLIED WARRANTIES OF MERCHANTABILITY, OR FITNESS FOR A PARTICULAR PURPOSE.
- 8. When using Renesas Electronics products, refer to the latest product information (data sheets, user's manuals, application notes, "General Notes for Handling and Using Semiconductor Devices" in the reliability handbook, etc.), and ensure that usage conditions are within the ranges specified by Renesas Electronics with respect to maximum ratings, operating power supply voltage range, heat dissipation characteristics, installation, etc. Renesas Electronics disclaims any and all liability for any malfunctions, failure or accident arising out of the use of Renesas Electronics products outside of such specified ranges.
- 9. Although Renesas Electronics endeavors to improve the quality and reliability of Renesas Electronics products, semiconductor products have specific characteristics, such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Unless designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not subject to radiation resistance design. You are responsible for implementing safety measures to guard against the possibility of bodily injury, injury or damage caused by fire, and/or danger to the public in the event of a failure or malfunction of Renesas Electronics products, such as safety design for hardware and software, including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult and impractical, you are responsible for evaluating the safety of the final products or systems manufactured by you.
- 10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. You are responsible for carefully and sufficiently investigating applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive, and using Renesas Electronics products in compliance with all these applicable laws and regulations. Renesas Electronics disclaims any and all liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
- 11. Renesas Electronics products and technologies shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You shall comply with any applicable export control laws and regulations promulgated and administered by the governments of any countries asserting jurisdiction over the parties or transactions.
- 12. It is the responsibility of the buyer or distributor of Renesas Electronics products, or any other party who distributes, disposes of, or otherwise sells or transfers the product to a third party, to notify such third party in advance of the contents and conditions set forth in this document.
- 13. This document shall not be reprinted, reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
- 14. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products.
- (Note1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its directly or indirectly controlled subsidiaries.
- (Note2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

(Disclaimer Rev.5.0-1)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

Contact Information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit: www.renesas.com/contact/